

XC6702 Series

ETR03074-003

36V input, 300mA low supply current, high speed voltage regulators

■ GENERAL DESCRIPTION

The XC6702 series are CMOS high-speed voltage regulator ICs with a 36 V input and low supply current. Internal circuitry includes a reference voltage supply, error amplifier, driver transistor, over-current protection circuit, overheat protection circuit, soft start circuit, and phase compensation circuit. The output voltage is fixed internally by laser trimming, and product selections from 1.8V to 18.0V are available. The over-current protection circuit and overheat protection circuit are built-in, and when the output current reaches the current limit or the junction temperature reaches the temperature limit, the corresponding circuit activates. The soft start circuit limits the rush current that flows from V_{IN} to V_{OUT} when the IC starts, enabling a stable startup sequence. The IC is put in the standby state by inputting L level into the CE pin, and the supply current is reduced to 0.1 μ A. A low-ESR capacitor such as a ceramic capacitor can also be used for C_L .

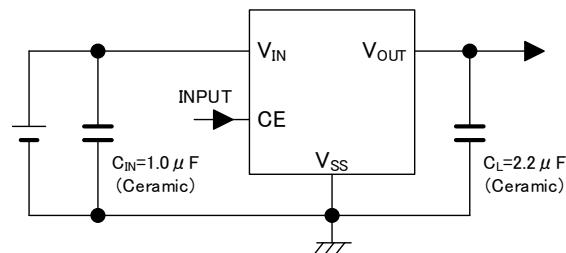
■ APPLICATIONS

- In-vehicle devices
- Industrial equipment
- Domestic electrical appliances
- Portable AV devices
- Various modules

■ FEATURES

Input voltage range	: 4.5V to 36.0V (absolute maximum rating 42.0V)
Peak voltage	: 46.0V (Transient \leq 400ms)
Output current	: 300mA
Output voltage range	: 1.8V to 18.0V (accuracy $\pm 1\%$) $V_{OUT} < 6.0V$, 0.1V step settings $V_{OUT} \geq 6.0V$, 0.5V step settings $\pm 50ppm/\text{°C}$ (TYP.)
Output voltage temperature characteristics	
Supply current	: 40 μ A (TYP.)
Dropout voltage	: 350mV @ $I_{OUT} = 100mA$, $V_{OUT} = 5.0V$
Ripple rejection ratio	: 65dB @ 1kHz
Standby current	: 0.1 μ A
Protection function	: Current limit, Short Protection Thermal shutdown
Addition function	: Soft start ON/OFF (Active High)
Output capacitor	: Ceramic capacitor (2.2 μ F)
Package	: USP-6C, SOT-89-5, SOP-8FD
Environment friendly features	: EU RoHS Directive compliant, lead free

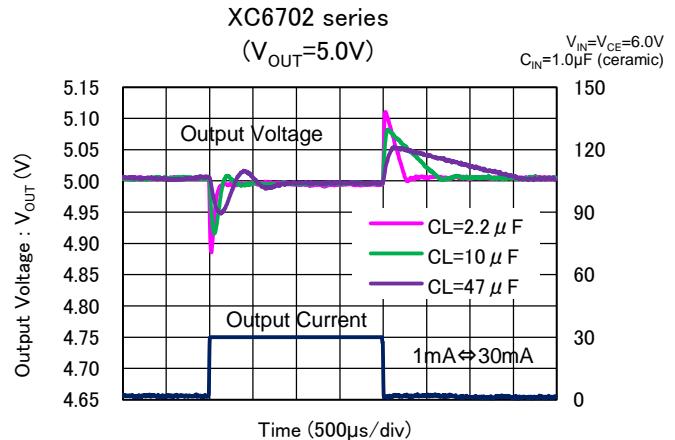
■ TYPICAL APPLICATION CIRCUIT



Our products are not designed to be Radiation-resistant.

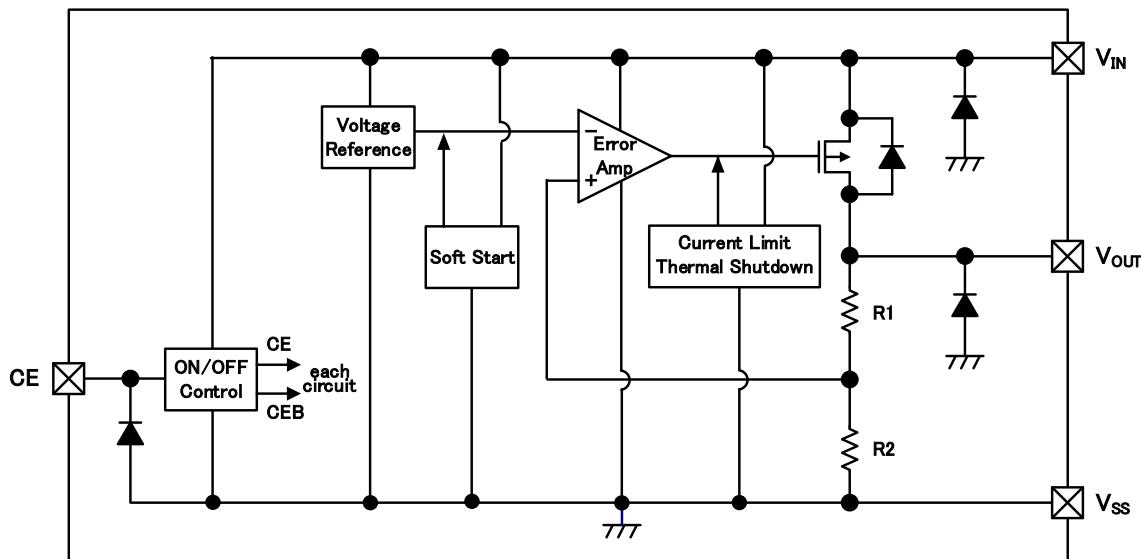
■ TYPICAL PERFORMANCE CHARACTERISTICS

Load Transient Response



■ BLOCK DIAGRAM

1) XC6702 Series D type



*The above diodes are diodes for electrostatic protection and parasitic diodes.

■ PRODUCT CLASSIFICATION

1) Ordering Information

XC6702①②③④⑤⑥-⑦^(*)1)

DESIGNATOR	ITEM	SYMBOL	DESCRIPTION
①	Type	D	Current Limit, Thermal Shutdown, Soft Start, ON/OFF Control
②③	Output Voltage ^(*)2)	18~J0 ^(*)3)	For the voltage within 1.8V~9.5V: e.g. 3.3V → ②=3, ③=3 5.0V → ②=5, ③=0 For the voltage within 10.0V~18.0V: e.g. 10.0V → ②=A, ③=0 12.5V → ②=C, ③=5 18.0V → ②=J, ③=0
④	Output Voltage Accuracy	1	± 1%
⑤⑥-⑦	Packages (Order Unit)	ER-G PR-G QR-G	USP-6C (3,000pcs/Reel) SOT-89-5 (1,000pcs /Reel) SOP-8FD (1,000pcs/Reel)

(*)1) "-G" indicates halogen and antimony free, as well as EU RoHS compliant.

(*)2) Output voltage setting steps are as follows:

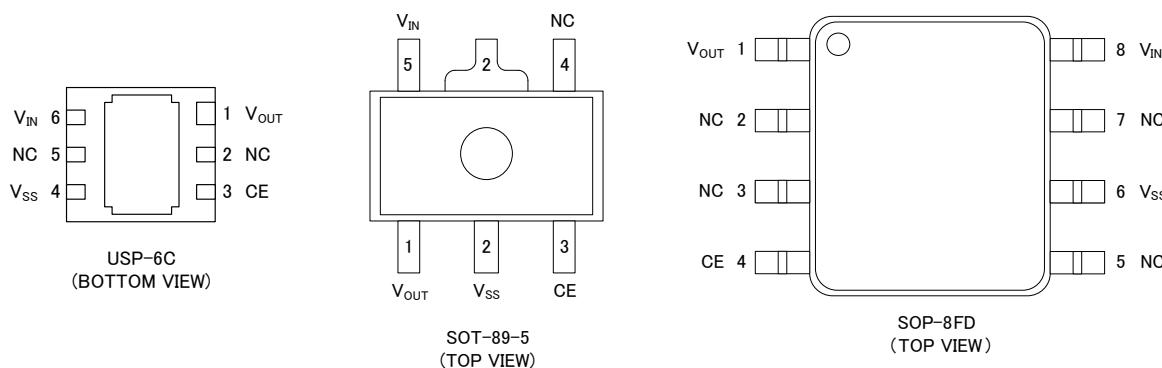
$V_{OUT} < 6.0V$ 0.1V-step settings

$V_{OUT} \geq 6.0V$ 0.5V-step settings

For other voltages, please contact your local Torex sales office or representative.

(*)3) For 10.0V to 18.0V, A to J excluding I are used in "②".

■PIN CONFIGURATION



* For mounting strength reinforcement and heat radiation of the USP-6C and SOP-8FD radiator plates, it is recommended that soldering be performed according to the reference pattern layout and reference metal mask design.

To fix the voltage of the radiator plate, connect to V_{ss} (Pin 4 of USP-6C or Pin 6 of SOP-8FD).

■PIN ASSIGNMENT

PIN NUMBER			PIN NAME	FUNCTIONS
USP-6C	SOT-89-5	SOP-8FD		
1	1	1	V _{OUT}	Output
2,5	4	2,3,5,7	NC	No Connection
3	3	4	CE	ON/OFF Control
4	2	6	V _{SS}	Ground
6	5	8	V _{IN}	Power Input

■PIN FUNCTION ASSIGNMENT

PIN NAME	SIGNAL	STATUS
CE	L	Stand-by
	H	Active
	OPEN	Unstable

* Avoid leaving the CE pin open; set to any fixed voltage.

■ ABSOLUTE MAXIMUM RATINGS

 $T_a=25^\circ\text{C}$

PARAMETER	SYMBOL	RATINGS	UNITS
Input Voltage	V_{IN}	-0.3~+42.0	V
Output Current	I_{OUT}	600 ^(*)1)	mA
Output Voltage	V_{OUT}	-0.3~ $V_{IN}+0.3$ or +42.0 ^(*)2)	V
CE Input Voltage	V_{CE}	-0.3~+42.0	V
Power Dissipation	USP-6C	120	mW
		1000 (when mounted on board) ^(*)3)	
		500	
	SOT-89-5	1300 (when mounted on board) ^(*)3)	
		300	
	SOP-8FD	1500 (when mounted on board) ^(*)3)	
Surge Voltage	V_{SURGE}	+46.0 ^(*)4)	V
Operating Ambient Temperature	T_{opr}	-40~+105	°C
Junction Temperature	T_j	-40~+125	°C
Storage Temperature	T_{stg}	-55~+125	°C

All voltage ratings are relative to V_{SS} .^(*)1) Use with I_{OUT} less than $P_d/(V_{IN}-V_{OUT})$.^(*)2) The maximum value is the lower of $V_{IN} + 0.3$ and +42.0.^(*)3) Reference data for continuous power dissipation when mounted on board.

For mounting conditions, refer to sections 27 to 29.

^(*)4) Transient \leq 400ms

■ ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	CONDITIONS	Ta=25°C			-40°C≤Ta≤105°C ⁽⁶⁾			UNITS	CIRCUIT
			MIN.	TYP.	MAX.	MIN.	TYP.	MAX.		
Input Voltage	V _{IN}		4.5	-	36.0	4.5	-	36.0	V	①
Output Voltage	V _{OUT(E)} ⁽¹⁾	I _{OUT} =10mA	x0.99	V _{OUT(T)} ⁽²⁾	x1.01	x0.96	V _{OUT(T)} ⁽²⁾	x1.04	V	①
Quiescent Current	I _{SS}	I _{OUT} =0mA	-	40	80	-	40	90	μA	②
Stand-by Current	I _{STB}	V _{IN} =36.0V, V _{CE} =V _{SS}	-	0.01	0.10	-	0.01	2.10	μA	③
Maximum Output Current ⁽³⁾	I _{OUTMAX}	V _{IN} =V _{OUT(T)} +2.0V	300	-	-	300	-	-	mA	①
Load Regulation	ΔV _{OUT}	V _{IN} =V _{OUT(T)} +2.0V 0.1mA≤I _{OUT} ≤300mA	-	V _{OUT(T)} ≤5.0V 60 85 V _{OUT(T)} >5.0V 60 130	-	V _{OUT(T)} ≤5.0V 60 230 V _{OUT(T)} >5.0V 60 275	-	mV	①	
Dropout Voltage	V _{DIF} ⁽⁴⁾	I _{OUT} =100mA	-	<E-1>		<E-1>		mV	①	
Line Regulation	ΔV _{OUT} / (ΔV _{IN} ·V _{OUT})	V _{OUT(T)} +0.5V≤V _{IN} ≤36.0V	-	0.01	0.03	-	0.01	0.03	%/V	①
Output Voltage Temperature Characteristics	ΔV _{OUT} / (ΔT _{OPR} ·V _{OUT})		-	±50	-	-	±50	-	ppm /°C	①
Ripple Rejection Ratio	PSRR	V _{IN} =V _{OUT(T)} +1.0V _{DC} +0.5V _{P-PAC} I _{OUT} =10mA, f=1kHz C _{IN} Unconnected	-	65	-	-	65	-	dB	④
Limit Current ⁽³⁾	I _{LIM}	V _{IN} =V _{OUT(T)} +2.0V V _{OUT} =V _{OUT(E)} ×0.95	370	460	-	310	460	-	mA	①
Short - Circuit Current	I _{SHORT}	V _{OUT} =V _{SS}	-	115	-	-	115	-	mA	①
Thermal Shutdown Detect Temperature	T _{TSD}	Junction Temperature	-	150	-	-	150	-	°C	①
Thermal Shutdown Release Temperature	T _{TSR}	Junction Temperature	-	140	-	-	140	-	°C	①
Thermal Shutdown Hysteresis Width	T _{TSD} -T _{TSR}	Junction Temperature	-	10	-	-	10	-	°C	①
Soft-Start Time ⁽⁵⁾	t _{SS}	V _{CE} =0V→V _{IN}	-	370	890	-	370	1100	μs	⑤
Inrush Current	I _{RUSH}	V _{CE} =0V→V _{IN}	-	V _{OUT(T)} ≤3.3V 55 95 3.3V<V _{OUT(T)} ≤5.0V 70 135 V _{OUT(T)} >5.0V 125 210	-	V _{OUT(T)} ≤3.3V 55 155 3.3V<V _{OUT(T)} ≤5.0V 70 215 V _{OUT(T)} >5.0V 125 330	-	mA	⑤	
CE "H" Level Voltage	V _{CEH}		2.5	-	36.0	2.5	-	36.0	V	⑥
CE "L" Level Voltage	V _{CEL}		V _{SS}	-	1.2	V _{SS}	-	1.2	V	⑥
CE "H" Level Current	I _{CEH}	V _{CE} =V _{IN} =36.0V	-0.10	-	0.10	-0.10	-	0.10	μA	⑥
CE "L" Level Current	I _{CCL}	V _{IN} =36.0V, V _{CE} =V _{SS}	-0.10	-	0.10	-0.10	-	0.10	μA	⑥

V_{IN}=V_{OUT(T)}+1.0V, V_{CE}=V_{IN}, I_{OUT}=1mA, C_{IN}=1.0μF, C_L=2.2μF unless otherwise specified.This parameter is tested on V_{IN}=4.5V if the input voltage is under 4.5V.⁽¹⁾ V_{OUT(E)} : Actual output voltage value.⁽²⁾ V_{OUT(T)} : Set output voltage value.⁽³⁾ Differences in heat dissipation when mounted may cause activation of thermal shutdown circuit, preventing attainment of maximum output current.⁽⁴⁾ V_{DIF} is defined as follows: V_{DIF}={V_{IN1}-V_{OUT1}}.V_{IN1} : As input voltage is gradually reduced, the input voltage at which V_{OUT1} is output.V_{OUT1} : 98% of output voltage when V_{IN} is input after stabilizing sufficiently at I_{OUT}=100mA.⁽⁵⁾ Time from input of voltage higher than CE "H" level voltage into CE pin until output voltage is V_{OUT(T)} × 0.9V or higher.⁽⁶⁾ The values under -40°C≤Ta≤105°C has been tested and guaranteed by design engineering.

■ ELECTRICAL CHARACTERISTICS (Continued)

Voltage Chart 1 <E-0>

NOMINAL OUTPUT VOLTAGE	<E-0>				
	Output Voltage $V_{OUT(E)}$ (V)				
	Ta=25°C		-40°C ≤ Ta ≤ 105°C		
$V_{OUT(T)}$ (V)	MIN.	MAX.	MIN.	MAX.	
1.8	1.782	1.818	1.728	1.872	
1.9	1.881	1.919	1.824	1.976	
2.0	1.980	2.020	1.920	2.080	
2.1	2.079	2.121	2.016	2.184	
2.2	2.178	2.222	2.112	2.288	
2.3	2.277	2.323	2.208	2.392	
2.4	2.376	2.424	2.304	2.496	
2.5	2.475	2.525	2.400	2.600	
2.6	2.574	2.626	2.496	2.704	
2.7	2.673	2.727	2.592	2.808	
2.8	2.772	2.828	2.688	2.912	
2.9	2.871	2.929	2.784	3.016	
3.0	2.970	3.030	2.880	3.120	
3.1	3.069	3.131	2.976	3.224	
3.2	3.168	3.232	3.072	3.328	
3.3	3.267	3.333	3.168	3.432	
3.4	3.366	3.434	3.264	3.536	
3.5	3.465	3.535	3.360	3.640	
3.6	3.564	3.636	3.456	3.744	
3.7	3.663	3.737	3.552	3.848	
3.8	3.762	3.838	3.648	3.952	
3.9	3.861	3.939	3.744	4.056	
4.0	3.960	4.040	3.840	4.160	
4.1	4.059	4.141	3.936	4.264	
4.2	4.158	4.242	4.032	4.368	
4.3	4.257	4.343	4.128	4.472	
4.4	4.356	4.444	4.224	4.576	
4.5	4.455	4.545	4.320	4.680	
4.6	4.554	4.646	4.416	4.784	
4.7	4.653	4.747	4.512	4.888	
4.8	4.752	4.848	4.608	4.992	
4.9	4.851	4.949	4.704	5.096	
5.0	4.950	5.050	4.800	5.200	

NOMINAL OUTPUT VOLTAGE	<E-0>				
	Output Voltage $V_{OUT(E)}$ (V)				
	Ta=25°C		-40°C ≤ Ta ≤ 105°C		
$V_{OUT(T)}$ (V)	MIN.	MAX.	MIN.	MAX.	
5.1	5.049	5.151	4.896	5.304	
5.2	5.148	5.252	4.992	5.408	
5.3	5.247	5.353	5.088	5.512	
5.4	5.346	5.454	5.184	5.616	
5.5	5.445	5.555	5.280	5.720	
5.6	5.544	5.656	5.376	5.824	
5.7	5.643	5.757	5.472	5.928	
5.8	5.742	5.858	5.568	6.032	
5.9	5.841	5.959	5.664	6.136	
6.0	5.940	6.060	5.760	6.240	
6.5	6.435	6.565	6.240	6.760	
7.0	6.930	7.070	6.720	7.280	
7.5	7.425	7.575	7.200	7.800	
8.0	7.920	8.080	7.680	8.320	
8.5	8.415	8.585	8.160	8.840	
9.0	8.910	9.090	8.640	9.360	
9.5	9.405	9.595	9.120	9.880	
10.0	9.900	10.100	9.600	10.400	
10.5	10.395	10.605	10.080	10.920	
11.0	10.890	11.110	10.560	11.440	
11.5	11.385	11.615	11.040	11.960	
12.0	11.880	12.120	11.520	12.480	
12.5	12.375	12.625	12.000	13.000	
13.0	12.870	13.130	12.480	13.520	
13.5	13.365	13.635	12.960	14.040	
14.0	13.860	14.140	13.440	14.560	
14.5	14.355	14.645	13.920	15.080	
15.0	14.850	15.150	14.400	15.600	
15.5	15.345	15.655	14.880	16.120	
16.0	15.840	16.160	15.360	16.640	
16.5	16.335	16.665	15.840	17.160	
17.0	16.830	17.170	16.320	17.680	
17.5	17.325	17.675	16.800	18.200	
18.0	17.820	18.180	17.280	18.720	

■ELECTRICAL CHARACTERISTICS (Continued)

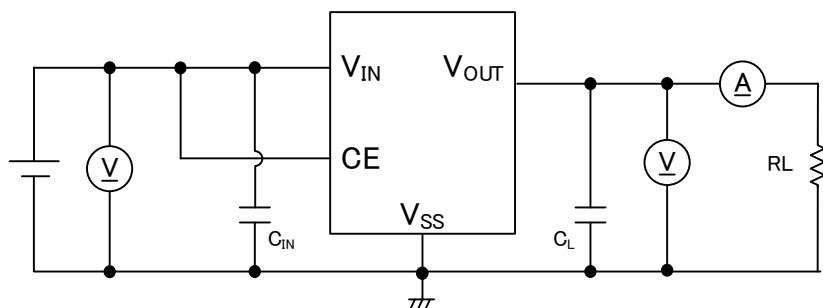
Voltage Chart 2 <E-1>

NOMINAL OUTPUT VOLTAGE	<E-1>				
	Dropout Voltage Vdif (mV) (I _{OUT} =100mA)				
	Ta=25°C		-40°C≤Ta≤105°C		
V _{OUT(T)} (V)	TYP.	MAX.	TYP.	MAX.	
1.8	1480	2700	1480	2700	
1.9	1440	2600	1440	2600	
2.0	1230	2500	1230	2500	
2.1		2400		2400	
2.2	1090	2300	1090	2300	
2.3		2200		2200	
2.4	1030	2100	1030	2100	
2.5		2000		2000	
2.6	670	1900	670	1900	
2.7		1800		1800	
2.8	460	1700	460	1700	
2.9		1600		1600	
3.0	450	1500	450	1500	
3.1		1400		1400	
3.2		1300		1300	
3.3	430	1200	430	1200	
3.4		1100		1100	
3.5		1000		1000	
3.6		900			
3.7		800			
3.8		700			
3.9		600			
4.0					
4.1					
4.2					
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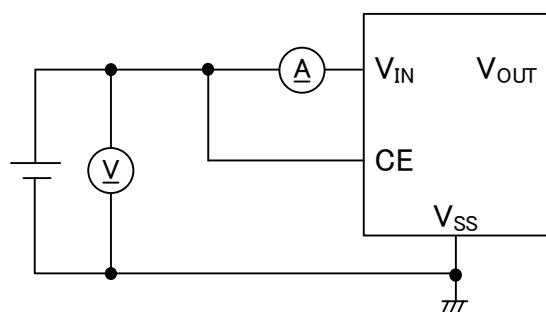
NOMINAL OUTPUT VOLTAGE	<E-1>				
	Dropout Voltage Vdif (mV) (I _{OUT} =100mA)				
	Ta=25°C		-40°C≤Ta≤105°C		
V _{OUT(T)} (V)	TYP.	MAX.	TYP.	MAX.	
5.0					
5.1					
5.2					
5.3					
5.4					
5.5					
5.6					
5.7					
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■ TEST CIRCUITS

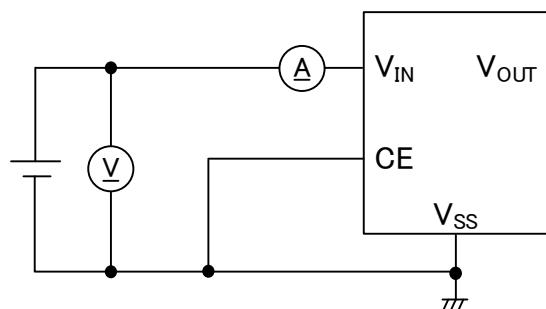
CIRCUIT①



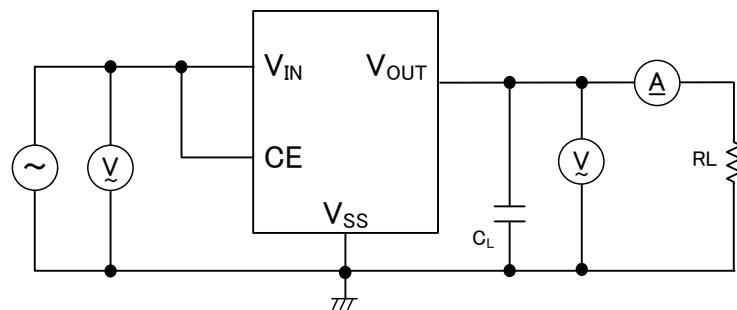
CIRCUIT②



CIRCUIT③

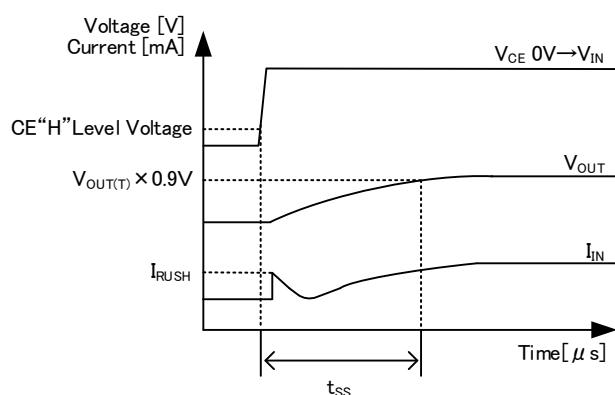
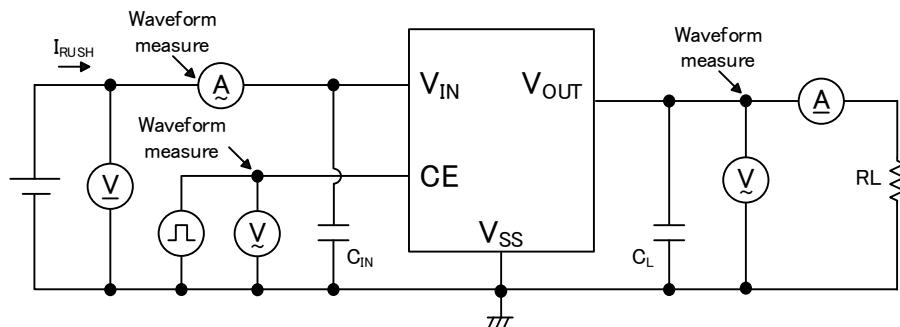


CIRCUIT④

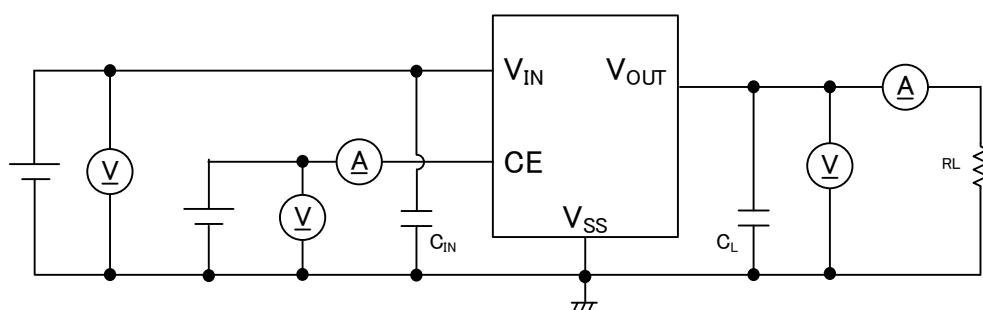


■ TEST CIRCUITS(Continued)

CIRCUIT⑤

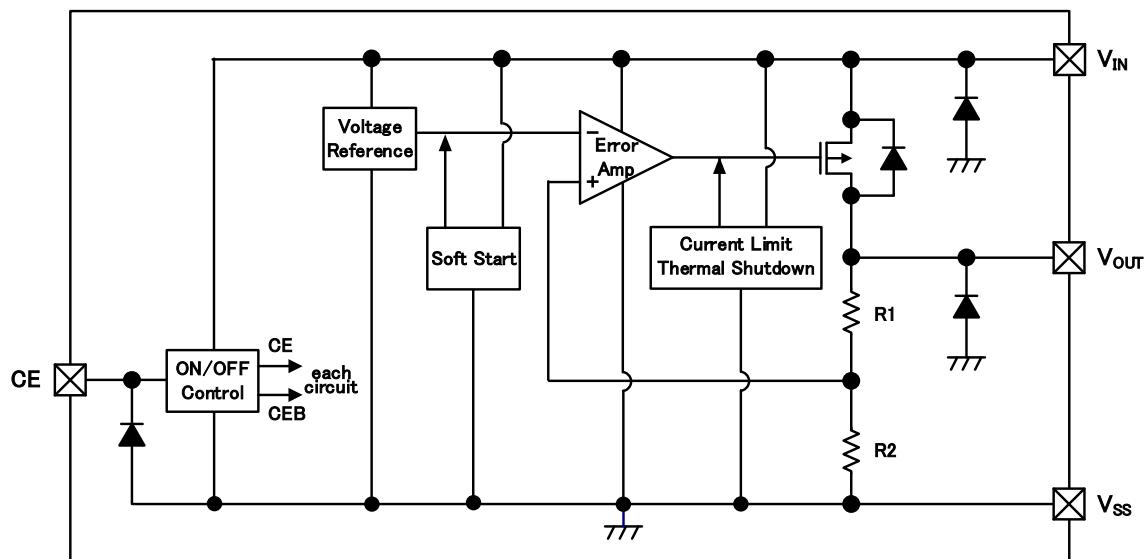


CIRCUIT⑥



■ OPERATIONAL EXPLANATION

The XC6702 series controls the output voltage by means of a scheme in which the error amplifier compares the voltage divided by R1 and R2 connected to the V_{out} pin with the voltage of the internal reference power supply. The output signal from the error amplifier makes the driver transistor connected to the V_{IN} pin drive, and negative feedback is applied to stabilize the output voltage.



XC6702 Series D Type

<Current limiting, short-circuit protection>

The XC6702 series incorporates a foldback circuit for current limiting (460mA TYP.) and short-circuit protection (115mA TYP.).

When the output current reaches the current limit, the output voltage falls and the output current is limited.

<Overheating protection>

The XC6702 series incorporates a thermal shutdown circuit for overheating protection.

When the junction temperature reaches the detection temperature (150°C TYP.), the driver transistor is forcibly turned off.

When the junction temperature falls to the release temperature (140°C TYP.) while the driver transistor remains in the off state, the driver transistor turns on (auto recovery) and regulation restarts. Unless the cause of rising temperature is removed, the driver transistor repeats on and off, and output waveform would be like consecutive pulses.

<CE pin>

The XC6702 series allows stopping of the IC internal circuit by a CE pin signal.

When the IC is in the stopped state by CE "L" level voltage input, the V_{out} pin is pulled down by R1 and R2 to the V_{ss} level.

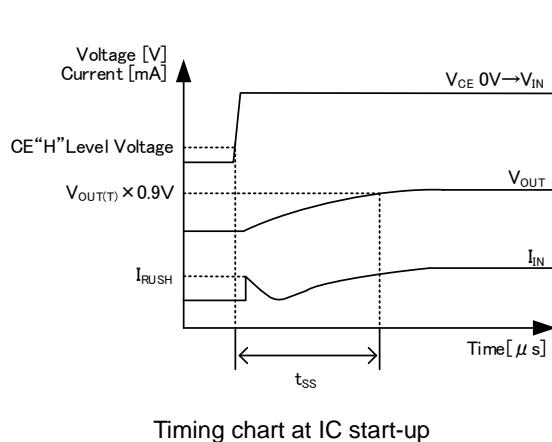
As long as the voltage input into the CE pin is within the CE pin voltage specification, the logic is established and there is no interference with operation.

If the CE pin is left open, operation is unspecified.

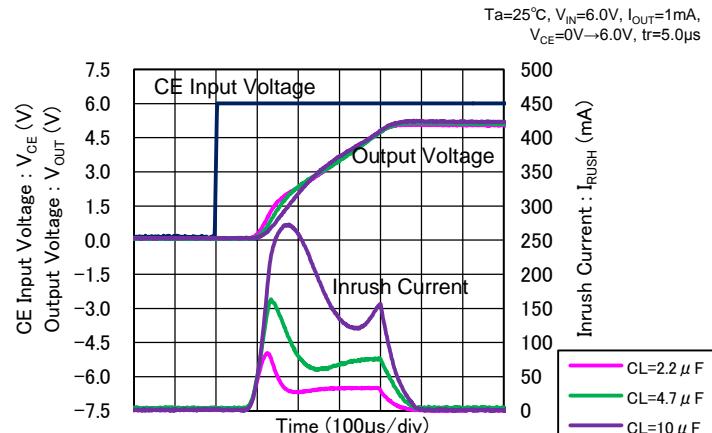
■OPERATIONAL EXPLANATION (Continued)

<Soft start>

The XC6702 series limits the rush current (I_{RUSH}) that suddenly flows from V_{IN} to V_{OUT} to charge the output capacitor (C_L) when the IC starts, and is also able to limit fluctuations of V_{IN} due to I_{RUSH} . The soft start time (t_{ss}) is optimized internally (370μs TYP.). The soft start time (t_{ss}) is defined as the V_{OUT} reaches 90% of $V_{OUT(T)}$ from the time when CE H threshold is input to the CE pin.



XC6702D501PR-G



Example of the inrush current wave form at IC start-up

<Low ESR capacitor support>

An internal phase compensation circuit is incorporated in the XC6702 series to enable a stable output voltage to be obtained even when a low ESR capacitor is used. To stabilize the effect of the phase compensation circuit, always connect the output capacitor (C_L) in direct proximity to the V_{OUT} pin and V_{SS} pin. In addition, to stabilize the input power, connect the input capacitor (C_{IN}) in direct proximity to the V_{IN} pin and V_{SS} pin. Refer to Table 1 for the recommended capacitance values to be connected.

Take particular care in selecting the capacitors for C_{IN} and C_L , as the bias dependence of the capacitor, the effect of capacitance loss due to temperature characteristics and other factors, and the effects of ESR may prevent stable phase compensation. Table 1 shows recommended capacitance values (MIN) for the actual bias and temperature conditions used for the capacitor. Select capacitances that satisfy Table 1 in all environments in which the product is to be used.

Table 1: Recommended capacitance values (MIN) of C_{IN} and C_L

OUTPUT VOLTAGE RANGE $V_{OUT(T)}$	INPUT CAPACITOR C_{IN}	OUTPUT CAPACITOR C_L
1.8V~18.0V	1.0μF	2.2μF

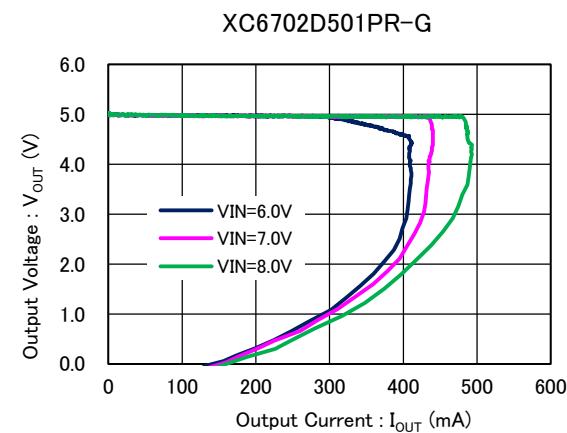
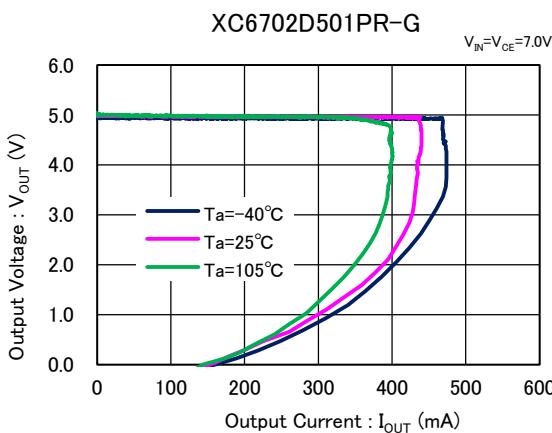
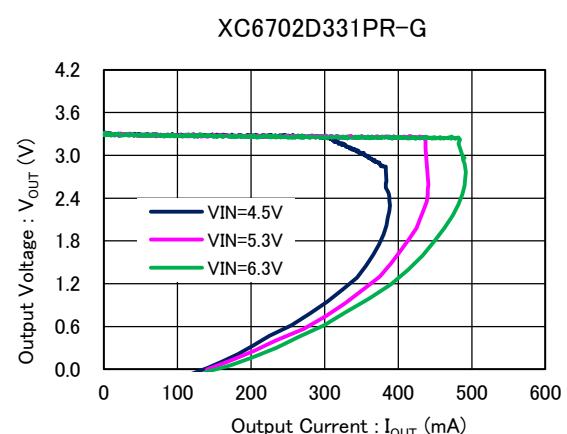
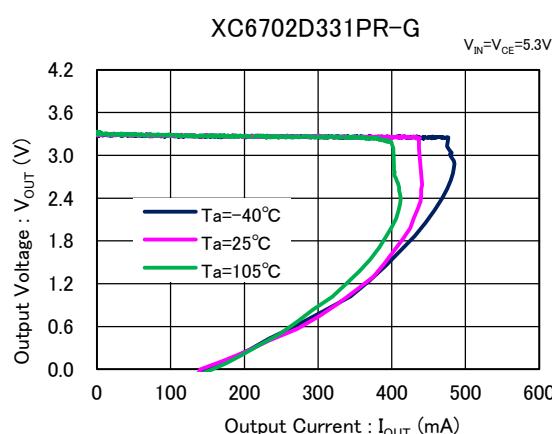
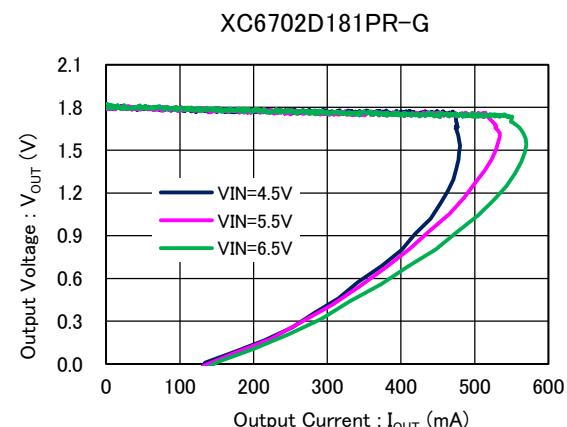
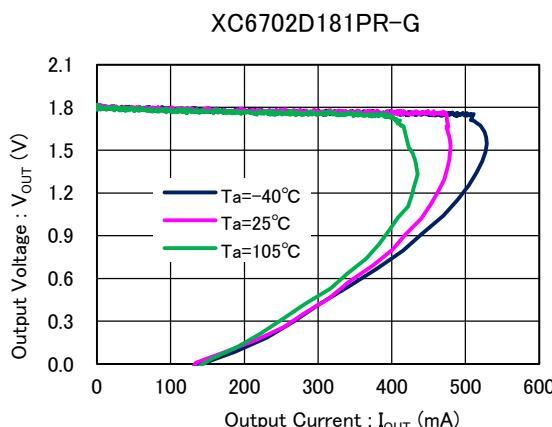
■NOTES ON USE

- 1) For temporary, transitional voltage drop or voltage rising phenomenon, the IC is liable to malfunction should the ratings be exceeded.
- 2) Where wiring impedance is high, operations may become unstable due to noise and/or phase lag depending on output current. Please keep the resistance low between V_{IN} and V_{SS} wiring in particular.
- 3) Please wire the input capacitor (C_{IN}) and the output capacitor (C_L) as close to the IC as possible.
- 4) Capacitances of these capacitors (C_{IN} , C_L) are decreased by the influences of bias voltage and ambient temperature. Care shall be taken for capacitor selection to ensure stability of phase compensation from the point of ESR influence.
- 5) Regarding the input transient response, the undershoot at the output voltage might be larger when input voltage variation is 5.0V or larger and the through-rate is 0.5V/ μ s or higher.
If the undershoot is not acceptable, please increase the output capacitance value and evaluate the system on your PCB well.
- 6) The IC goes into “undefined state” if the CE pin is not connected (Open state).
The CE pin voltage should be fixed in low or high for stable operation.
- 7) In general, semiconductor components have a possibility to have variation of electrical specifications due to the (cosmic) radiation exposure. Therefore this product has the same possibility. Please inform us in advance if your system might have a possibility to be exposed to the (cosmic) radiation in the production process (assembly, test, etc.).
- 8) Torex places an importance on improving our products and their reliability.
We request that users incorporate fail-safe designs and post-aging prevention treatment when using Torex products in their systems.

■ TYPICAL PERFORMANCE CHARACTERISTICS

T_a=25°C, V_{IN}=V_{OUT}(T) + 1.0V, V_{CE}=V_{IN}, I_{OUT}=1mA, C_{IN}=1.0μF, C_L=2.2μF(ceramic) unless otherwise specified.
This parameter is tested on V_{IN}=4.5V if the input voltage is under 4.5V.

(1) Output Voltage vs. Output Current

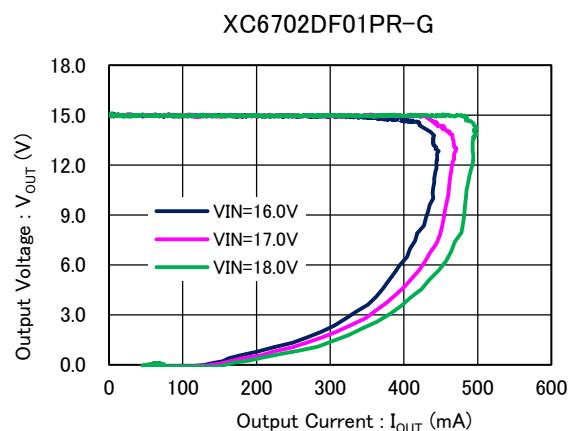
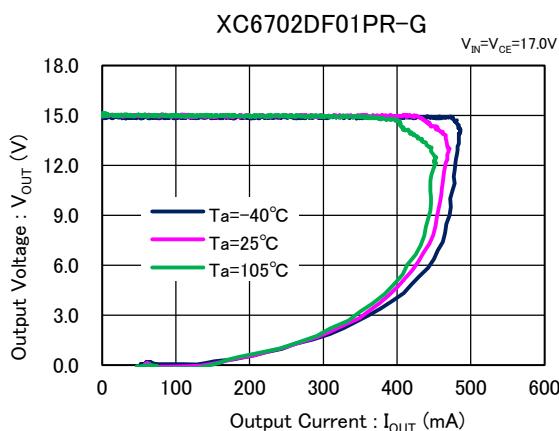


* Mount conditions affect heat dissipation. Thermal shutdown may start to operate.

■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

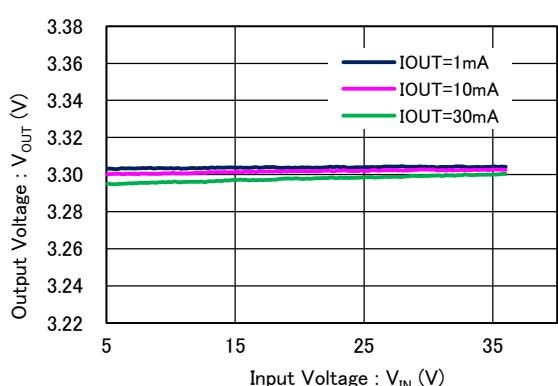
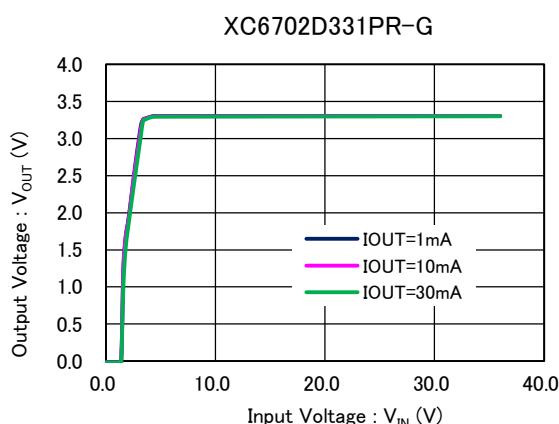
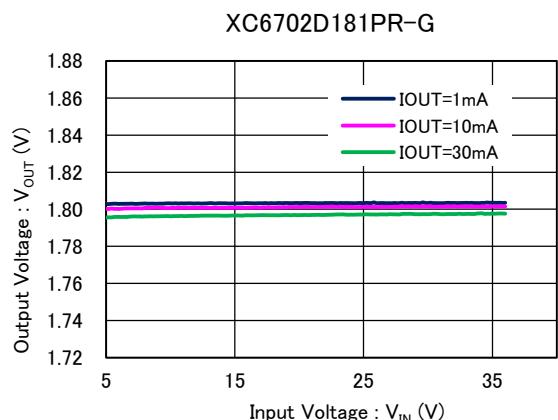
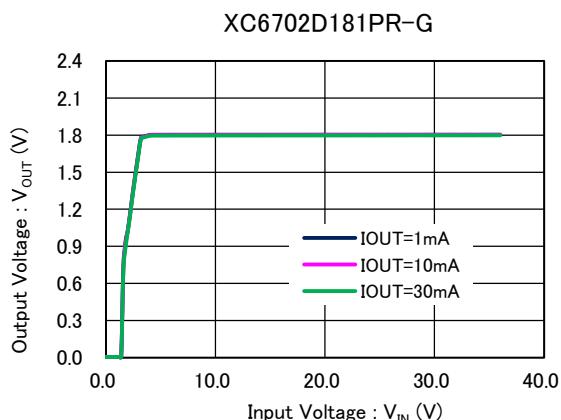
Ta=25°C, $V_{IN}=V_{OUT}(T) + 1.0V$, $V_{CE}=V_{IN}$, $I_{OUT}=1mA$, $C_{IN}=1.0\mu F$, $C_L=2.2\mu F$ (ceramic) unless otherwise specified.
This parameter is tested on $V_{IN}=4.5V$ if the input voltage is under 4.5V.

(1) Output Voltage vs. Output Current



* Mount conditions affect heat dissipation. Thermal shutdown may start to operate.

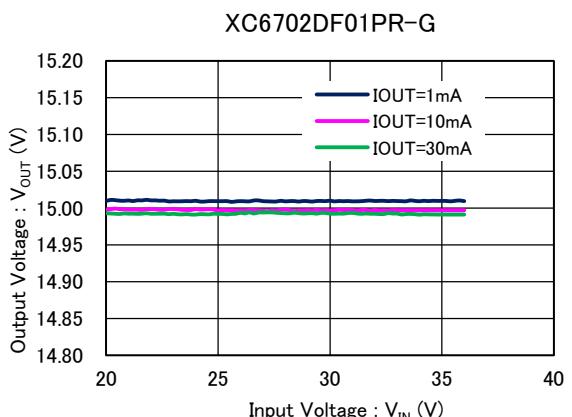
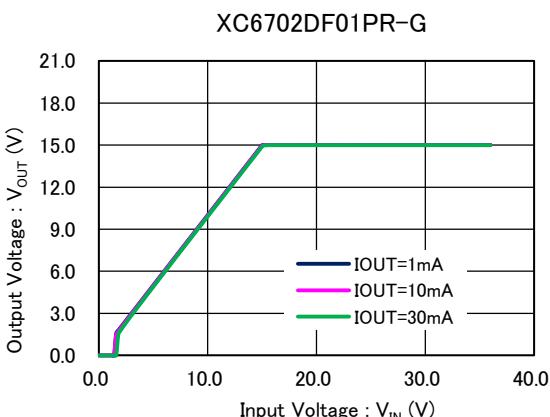
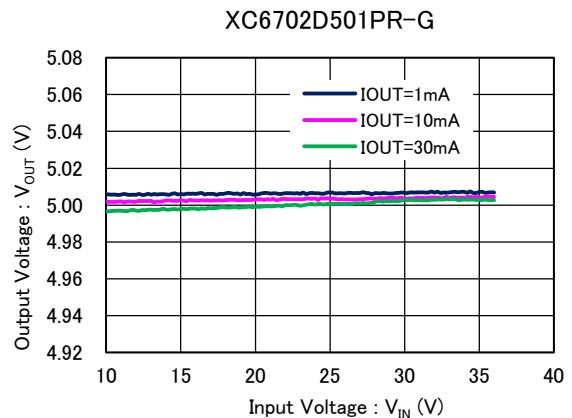
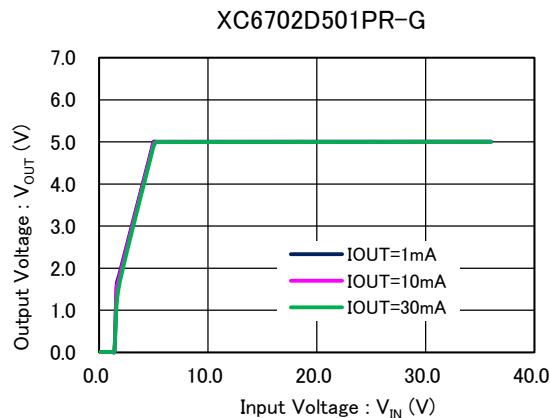
(2) Output Voltage vs. Input Voltage



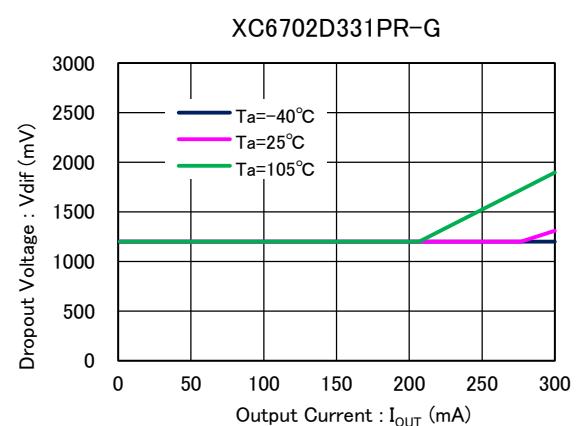
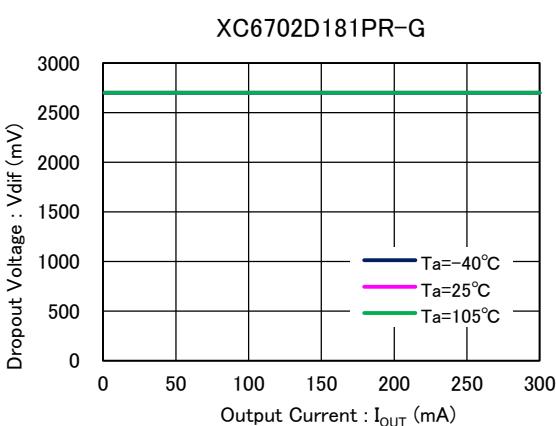
■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

$T_a=25^\circ\text{C}$, $V_{IN}=V_{OUT}(T) + 1.0\text{V}$, $V_{CE}=V_{IN}$, $I_{OUT}=1\text{mA}$, $C_{IN}=1.0\mu\text{F}$, $C_L=2.2\mu\text{F}$ (ceramic) unless otherwise specified.
This parameter is tested on $V_{IN}=4.5\text{V}$ if the input voltage is under 4.5V.

(2) Output Voltage vs. Input Voltage



(3) Dropout Voltage vs. Output Current



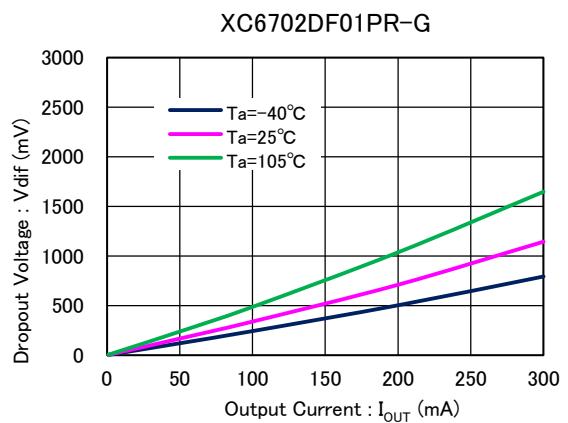
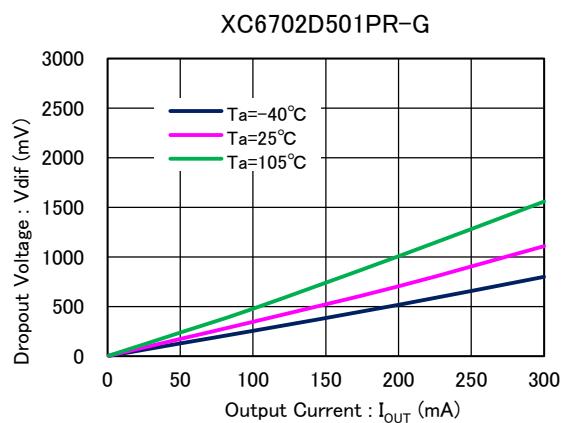
* Mount conditions affect heat dissipation. Thermal shutdown may start to operate.

■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

Ta=25°C, $V_{IN}=V_{OUT}(T) + 1.0V$, $V_{CE}=V_{IN}$, $I_{OUT}=1mA$, $C_{IN}=1.0\mu F$, $C_L=2.2\mu F$ (ceramic) unless otherwise specified.

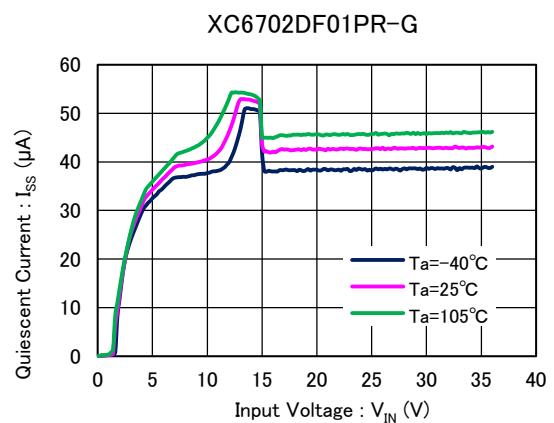
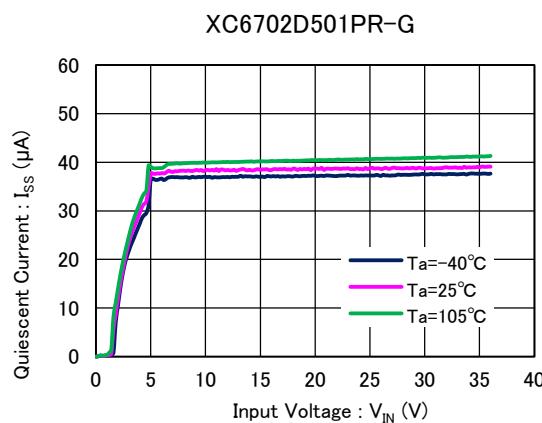
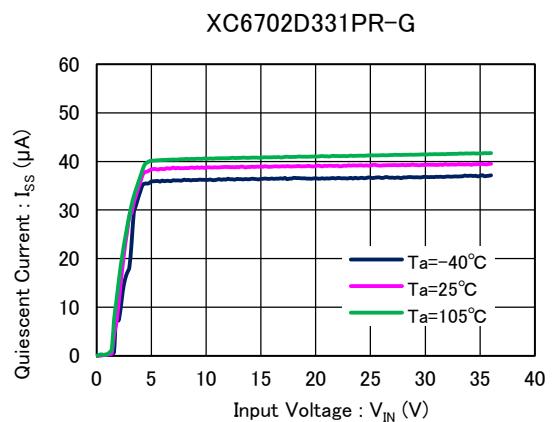
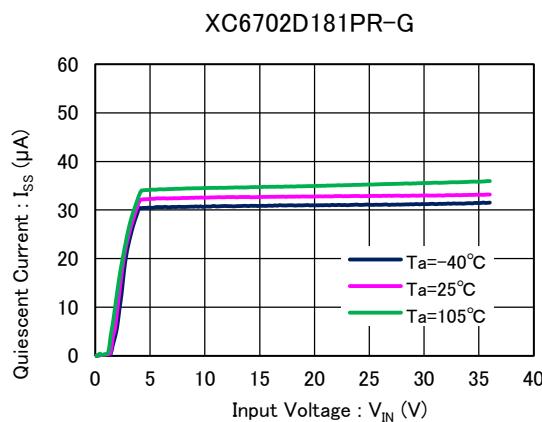
This parameter is tested on $V_{IN}=4.5V$ if the input voltage is under 4.5V.

(3) Dropout Voltage vs. Output Current



* Mount conditions affect heat dissipation. Thermal shutdown may start to operate.

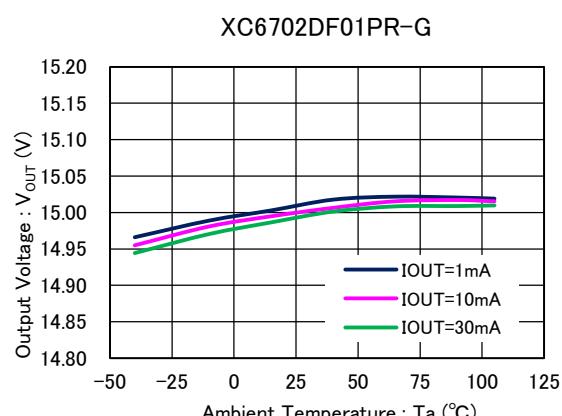
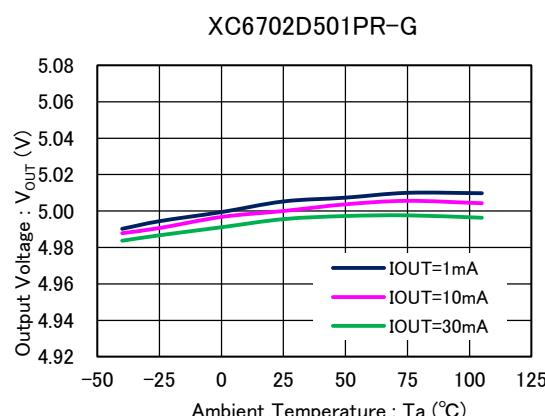
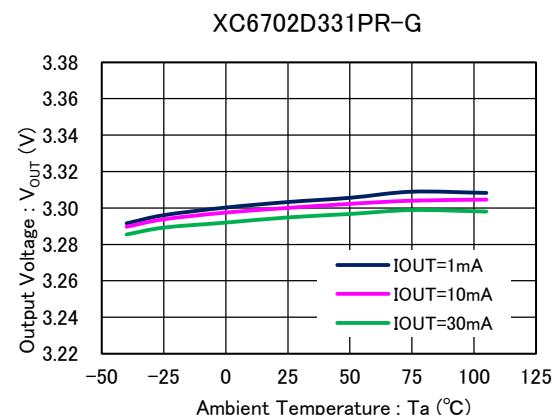
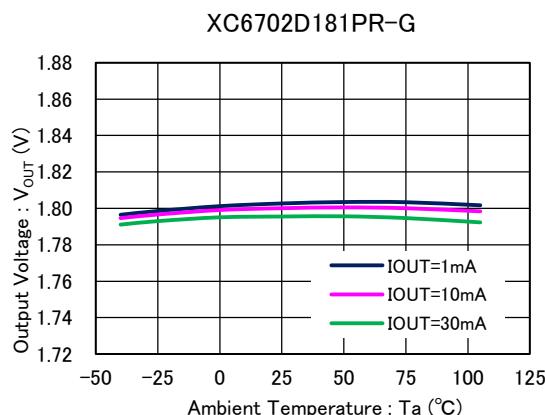
(4) Quiescent Current vs. Input Voltage



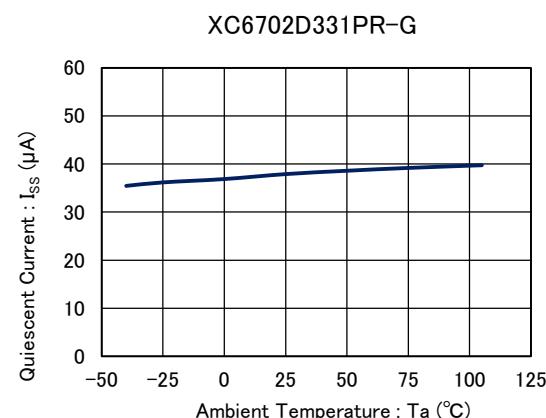
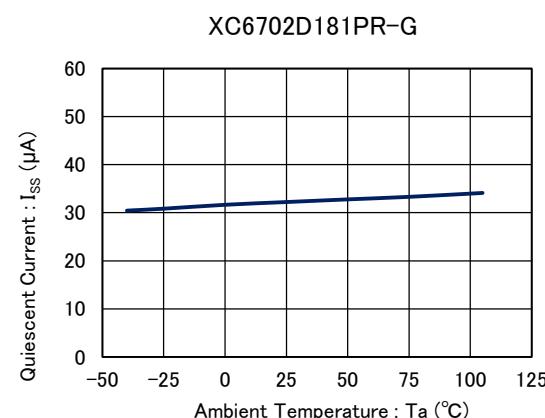
■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

$T_a=25^\circ\text{C}$, $V_{IN}=V_{OUT}(T) + 1.0\text{V}$, $V_{CE}=V_{IN}$, $I_{OUT}=1\text{mA}$, $C_{IN}=1.0\mu\text{F}$, $C_L=2.2\mu\text{F}$ (ceramic) unless otherwise specified.
This parameter is tested on $V_{IN}=4.5\text{V}$ if the input voltage is under 4.5V.

(5) Output Voltage vs. Ambient Temperature



(6) Quiescent Current vs. Ambient Temperature

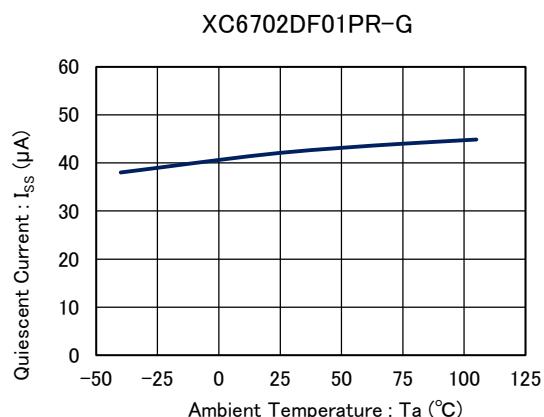
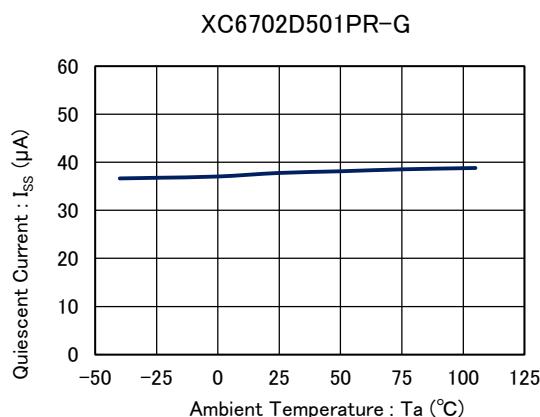


■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

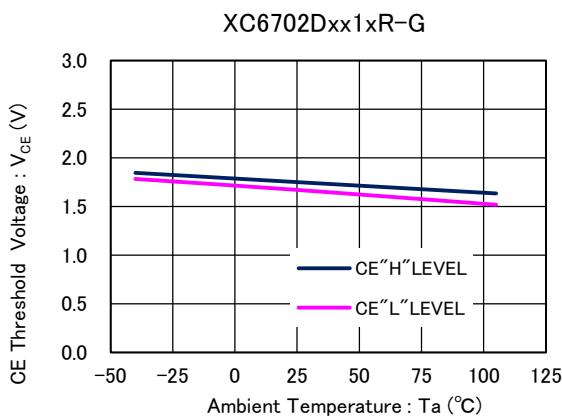
Ta=25°C, V_{IN}=V_{OUT}(T) + 1.0V, V_{CE}=V_{IN}, I_{OUT}=1mA, C_{IN}=1.0μF, C_L=2.2μF(ceramic) unless otherwise specified.

This parameter is tested on V_{IN}=4.5V if the input voltage is under 4.5V.

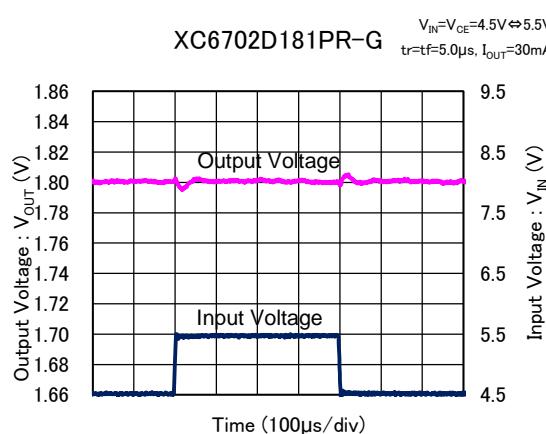
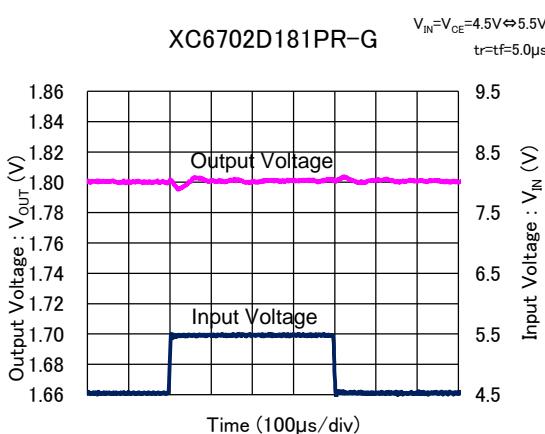
(6) Quiescent Current vs. Ambient Temperature



(7) CE Threshold Voltage vs. Ambient Temperature



(8) Input Transient Response

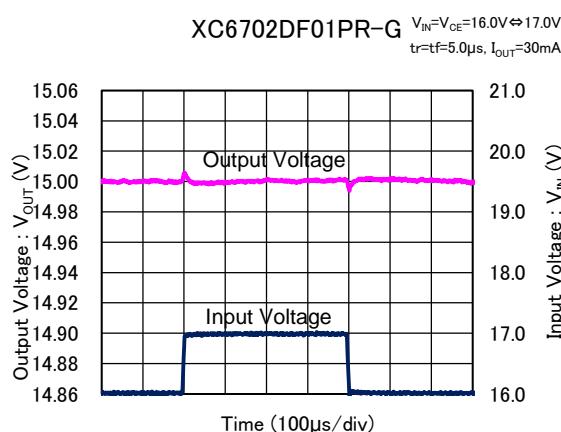
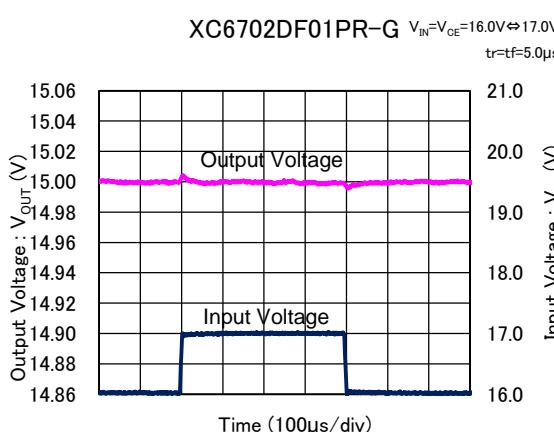
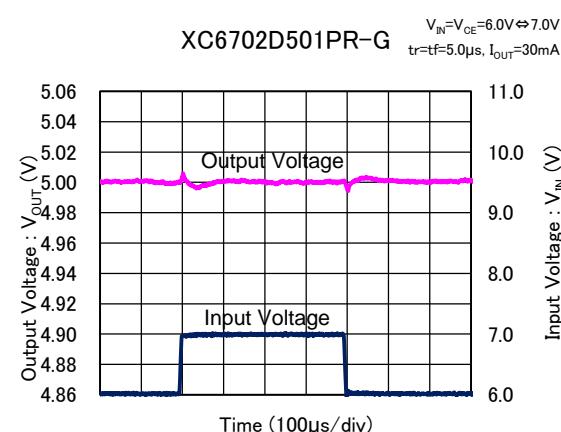
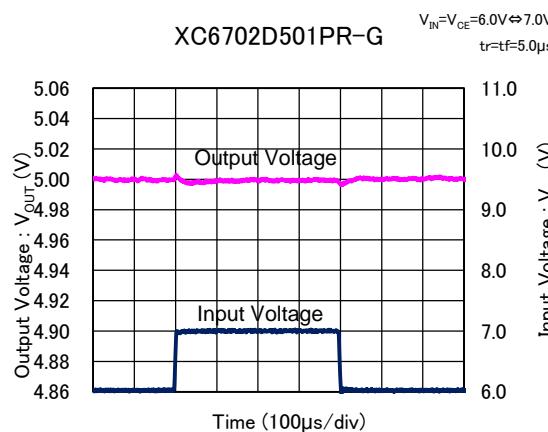
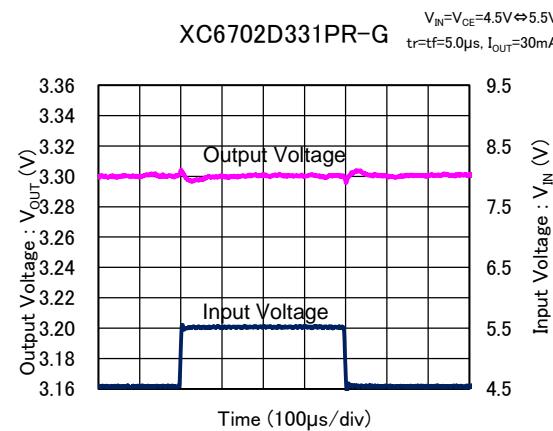
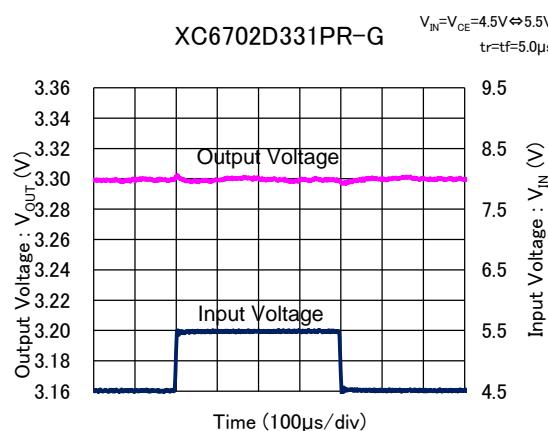


■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

Ta=25°C, V_{IN}=V_{OUT(T)} + 1.0V, V_{CE}=V_{IN}, I_{OUT}=1mA, C_{IN}=1.0μF, C_L=2.2μF(ceramic) unless otherwise specified.

This parameter is tested on V_{IN}=4.5V if the input voltage is under 4.5V.

(8) Input Transient Response

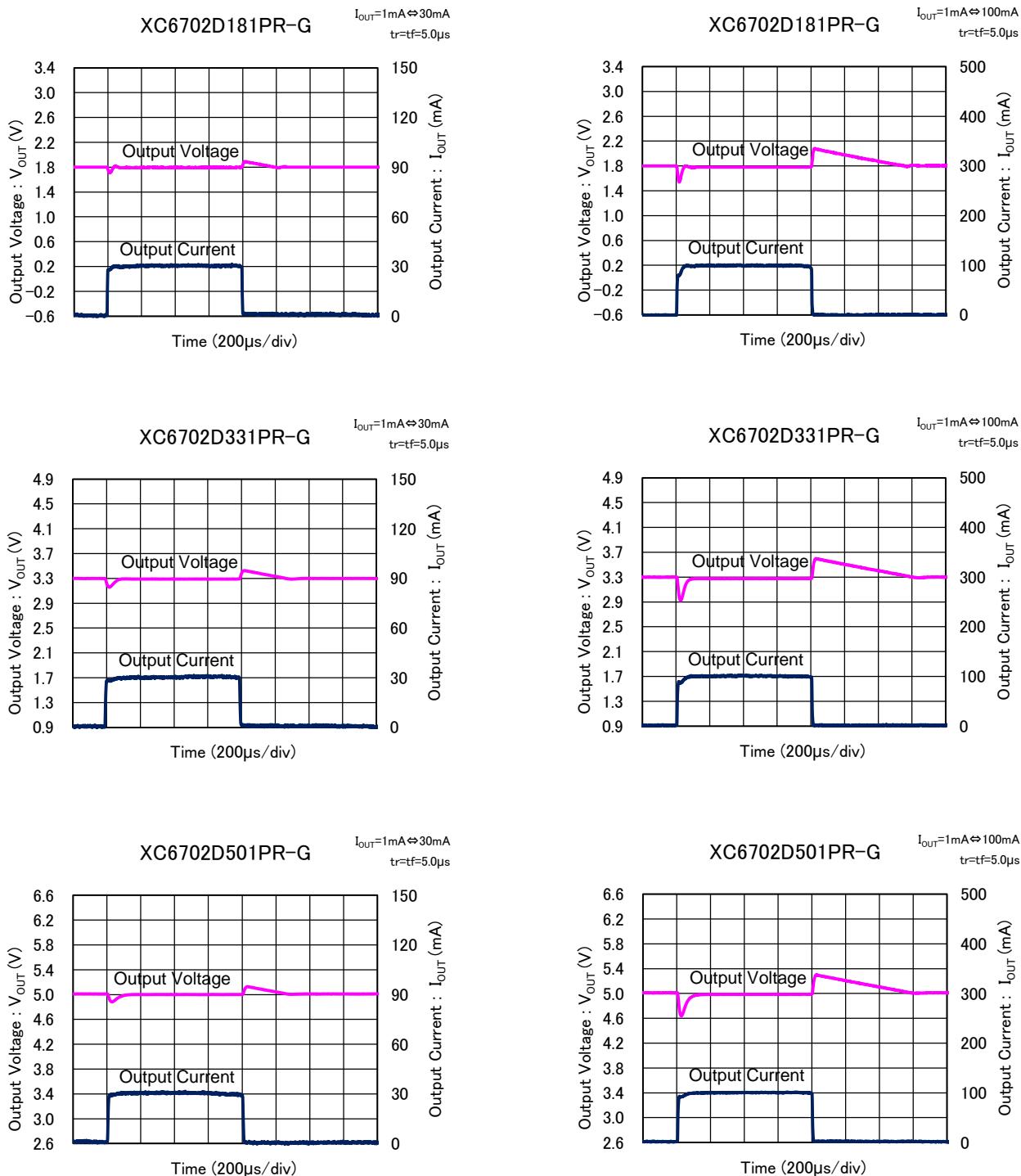


■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

$T_a=25^\circ\text{C}$, $V_{IN}=V_{OUT}(T) + 1.0\text{V}$, $V_{CE}=V_{IN}$, $I_{OUT}=1\text{mA}$, $C_{IN}=1.0\mu\text{F}$, $C_L=2.2\mu\text{F}$ (ceramic) unless otherwise specified.

This parameter is tested on $V_{IN}=4.5\text{V}$ if the input voltage is under 4.5V.

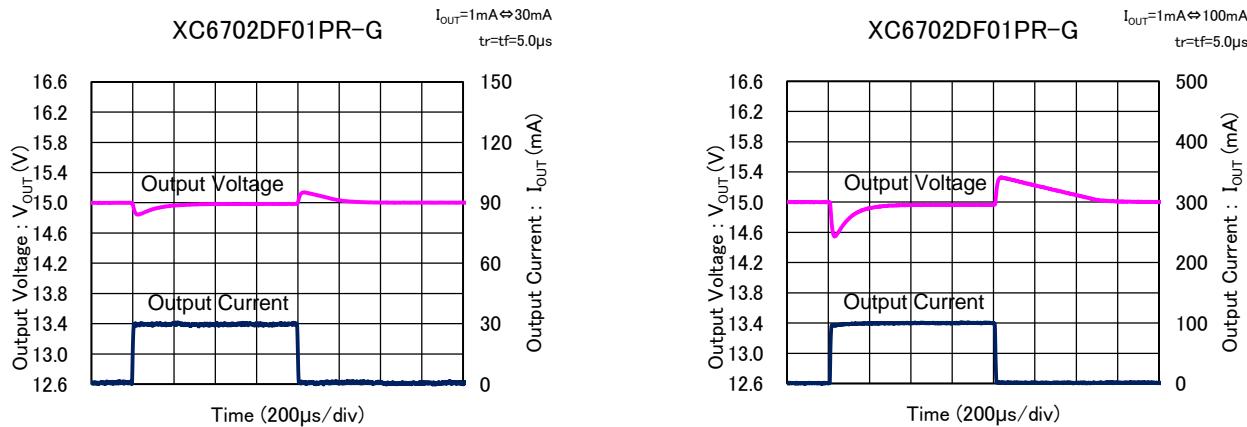
(9) Load Transient Response



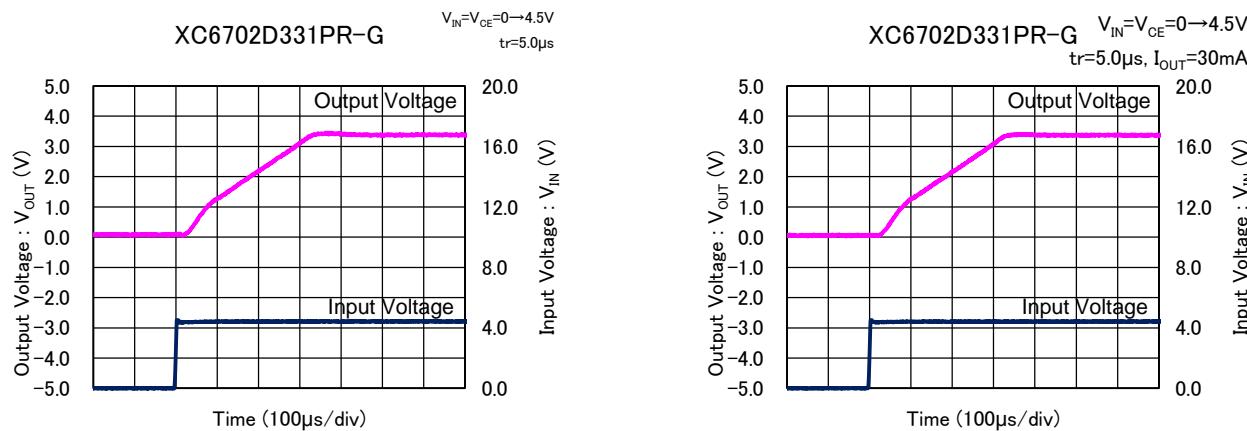
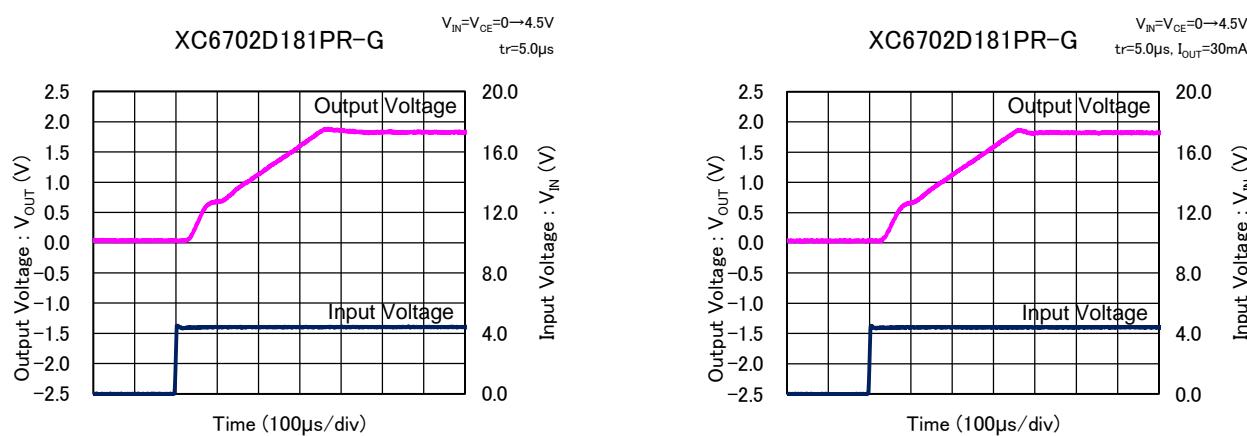
■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

Ta=25°C, $V_{IN}=V_{OUT}(T) + 1.0V$, $V_{CE}=V_{IN}$, $I_{OUT}=1mA$, $C_{IN}=1.0\mu F$, $C_L=2.2\mu F$ (ceramic) unless otherwise specified.
This parameter is tested on $V_{IN}=4.5V$ if the input voltage is under 4.5V.

(9) Load Transient Response



(10) Input Rising Response Time

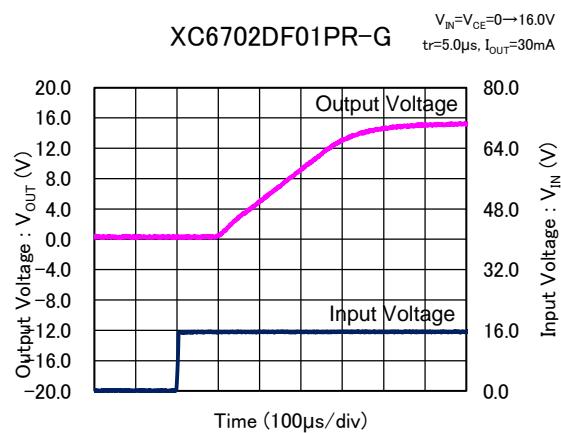
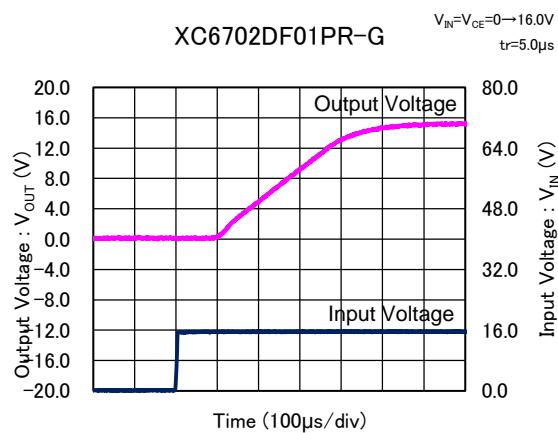
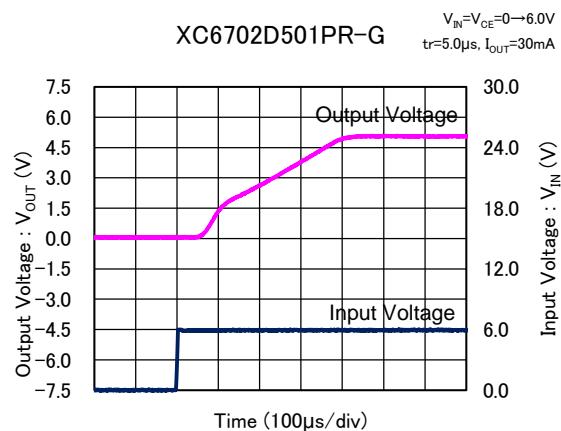
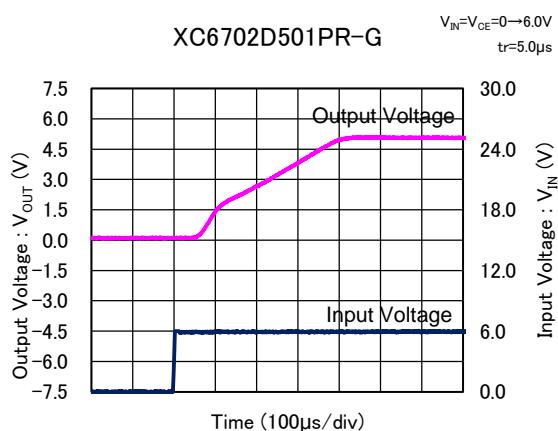


■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

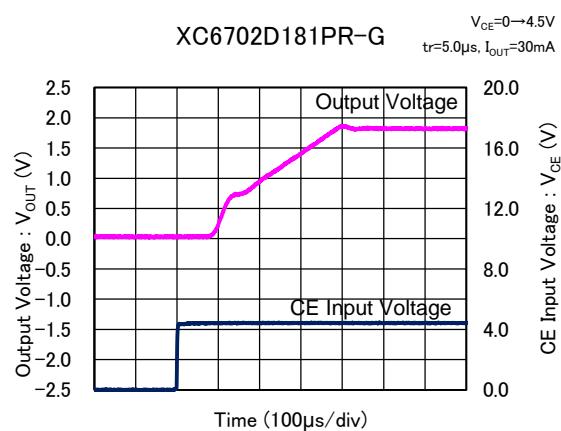
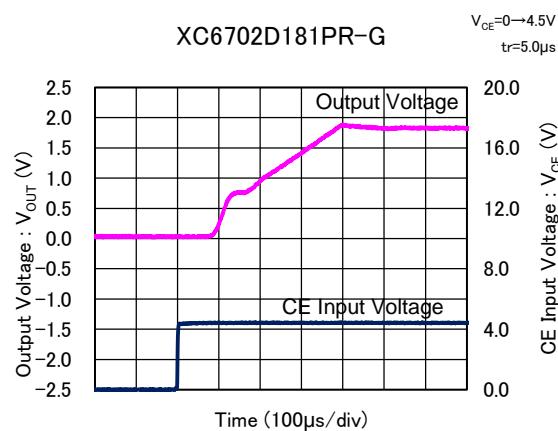
$T_a=25^\circ\text{C}$, $V_{IN}=V_{OUT}(T) + 1.0\text{V}$, $V_{CE}=V_{IN}$, $I_{OUT}=1\text{mA}$, $C_{IN}=1.0\mu\text{F}$, $C_L=2.2\mu\text{F}$ (ceramic) unless otherwise specified.

This parameter is tested on $V_{IN}=4.5\text{V}$ if the input voltage is under 4.5V.

(10) Input Rising Response Time



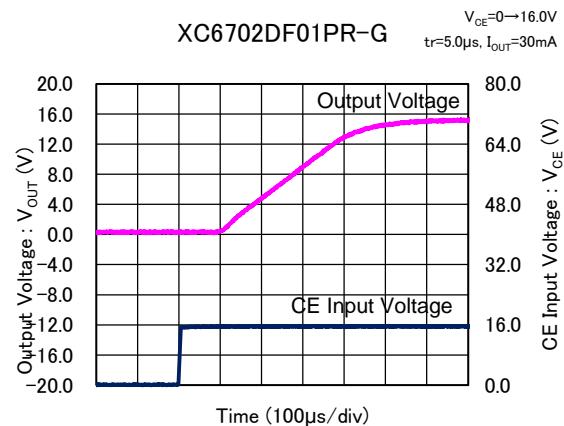
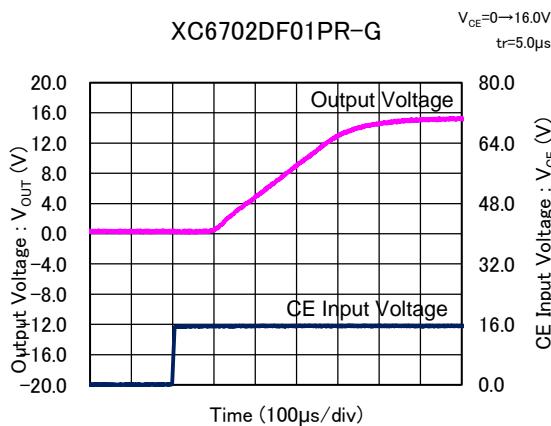
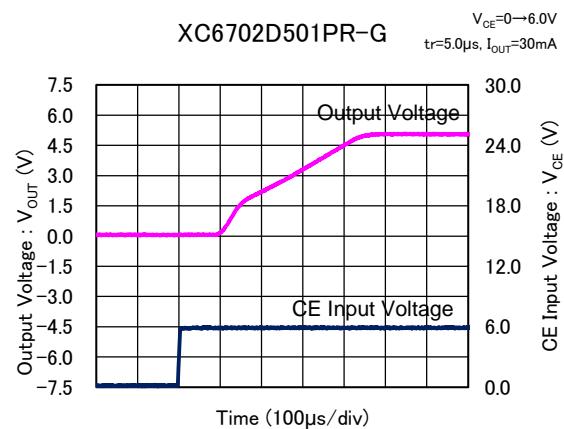
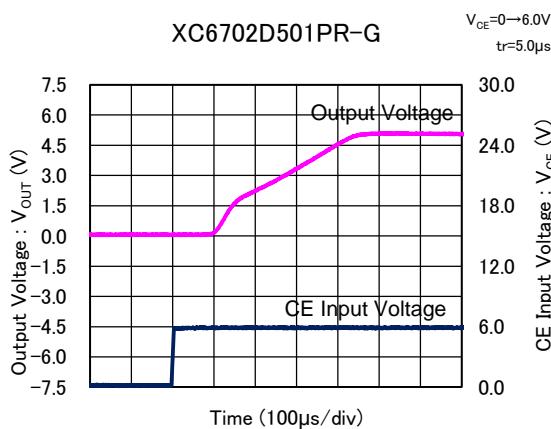
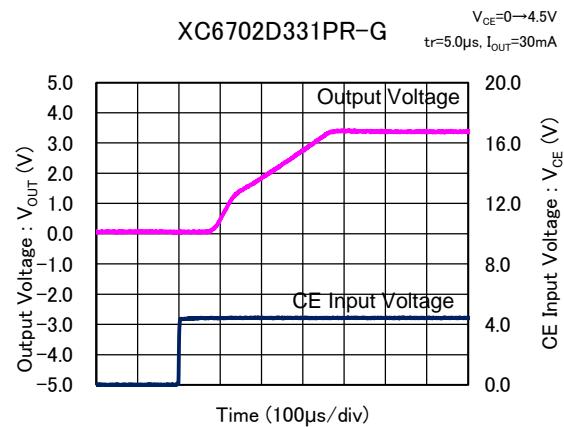
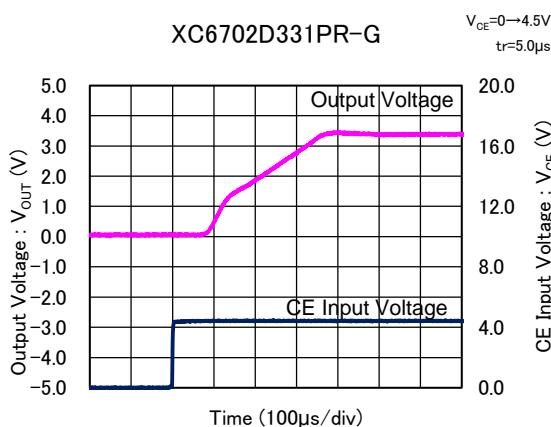
(11) CE Rising Response Time



■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

$T_a=25^\circ\text{C}$, $V_{IN}=V_{OUT}(T) + 1.0\text{V}$, $V_{CE}=V_{IN}$, $I_{OUT}=1\text{mA}$, $C_{IN}=1.0\mu\text{F}$, $C_L=2.2\mu\text{F}$ (ceramic) unless otherwise specified.
This parameter is tested on $V_{IN}=4.5\text{V}$ if the input voltage is under 4.5V.

(11) CE Rising Response Time

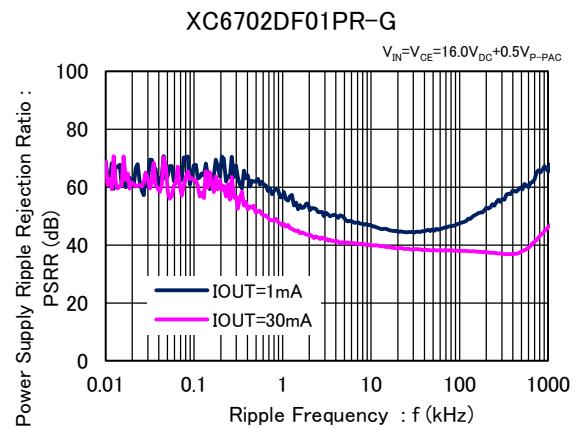
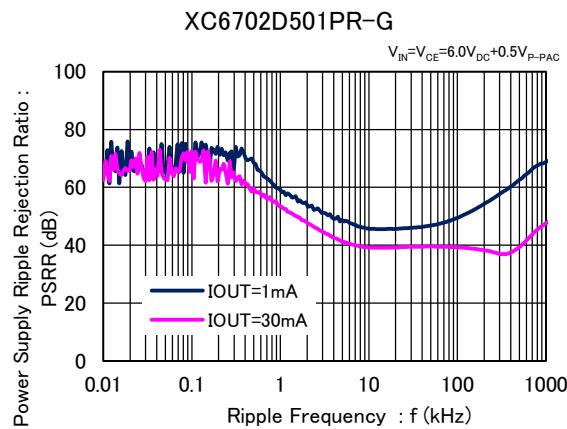
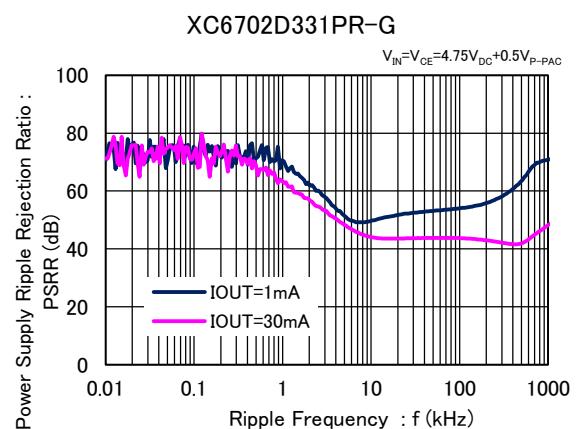
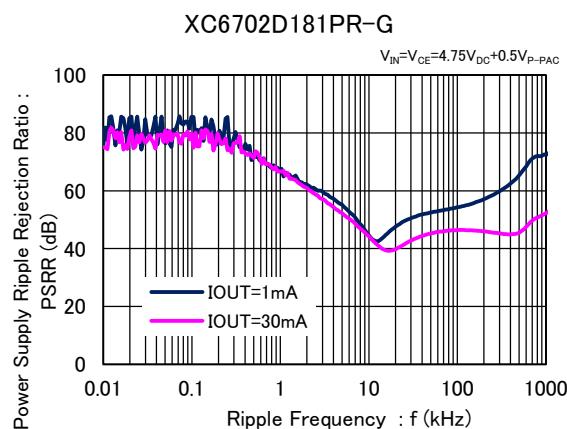


■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

$T_a=25^\circ\text{C}$, $V_{IN}=V_{OUT}(T) + 1.0\text{V}$, $V_{CE}=V_{IN}$, $I_{OUT}=1\text{mA}$, $C_{IN}=1.0\mu\text{F}$, $C_L=2.2\mu\text{F}$ (ceramic) unless otherwise specified.

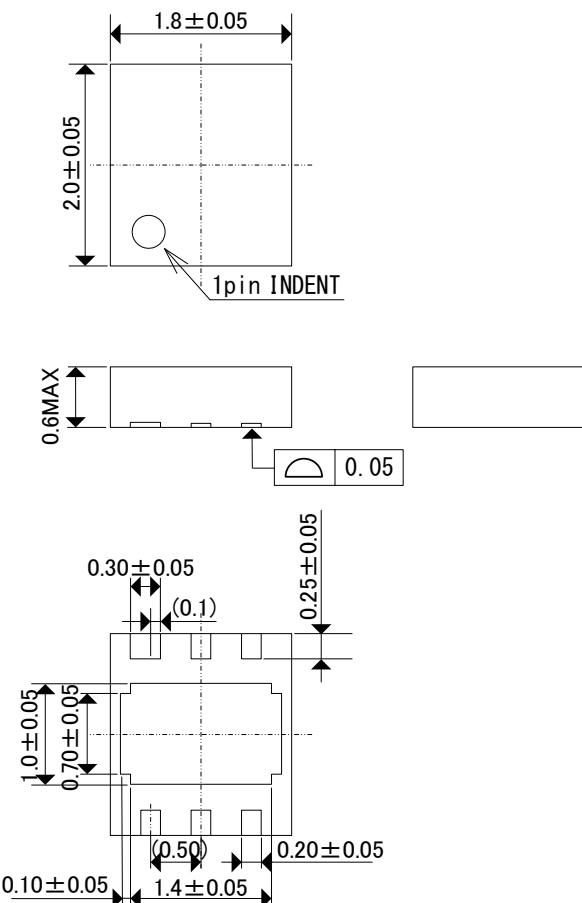
This parameter is tested on $V_{IN}=4.5\text{V}$ if the input voltage is under 4.5V.

(12) Power Supply Ripple Rejection Ratio

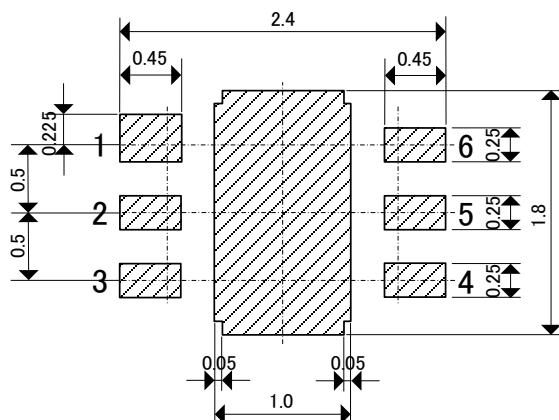


■PACKAGING INFORMATION

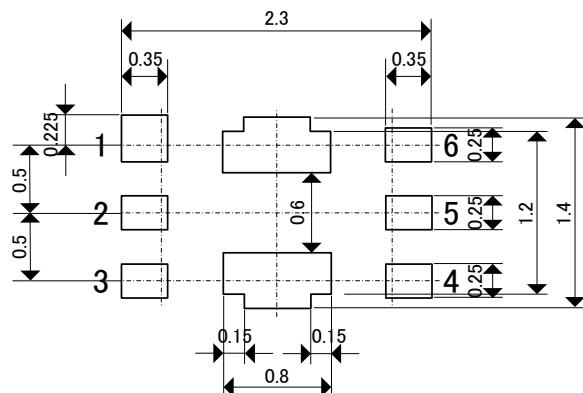
●USP-6C (unit: mm)



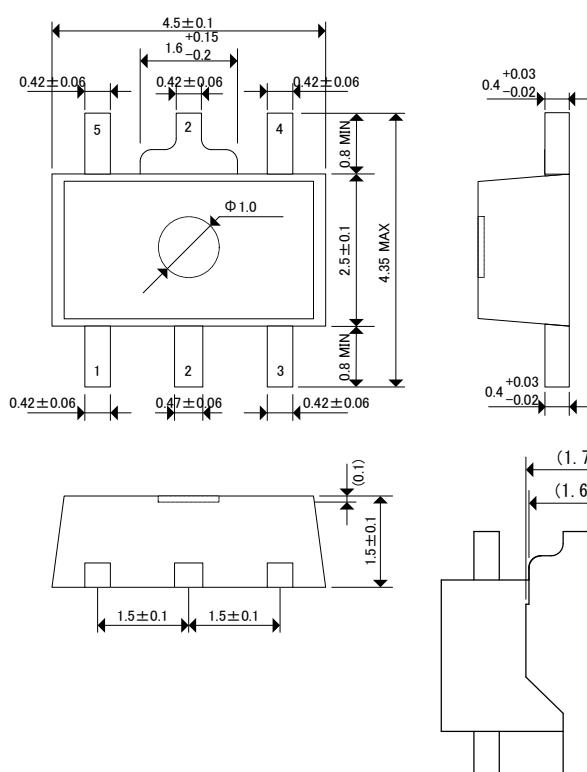
●USP-6C Reference Pattern Layout (unit: mm)



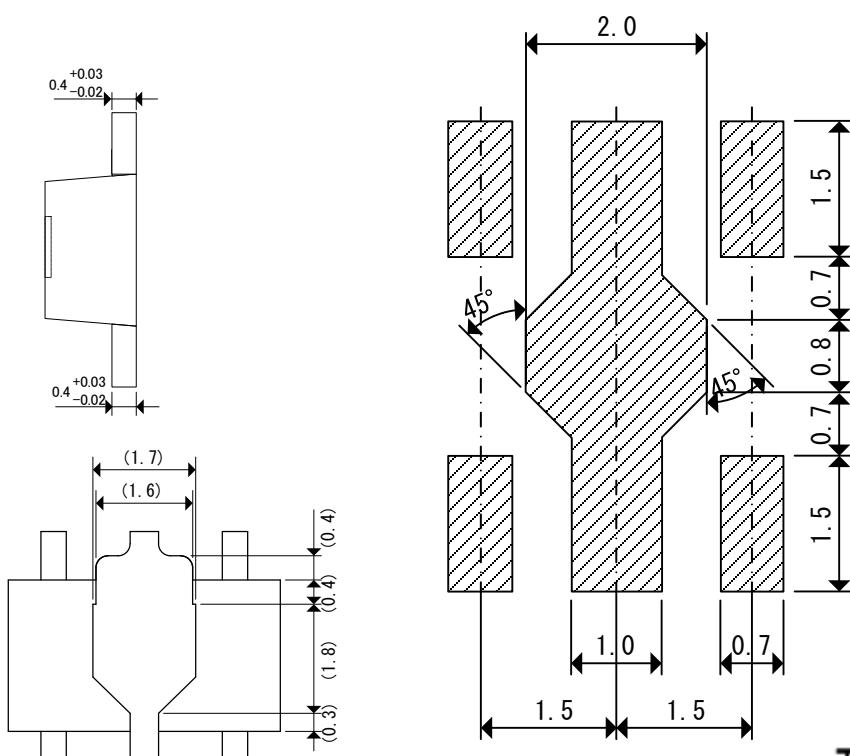
●USP-6C Reference Metal Mask Design (unit: mm)



●SOT-89-5 (unit: mm)

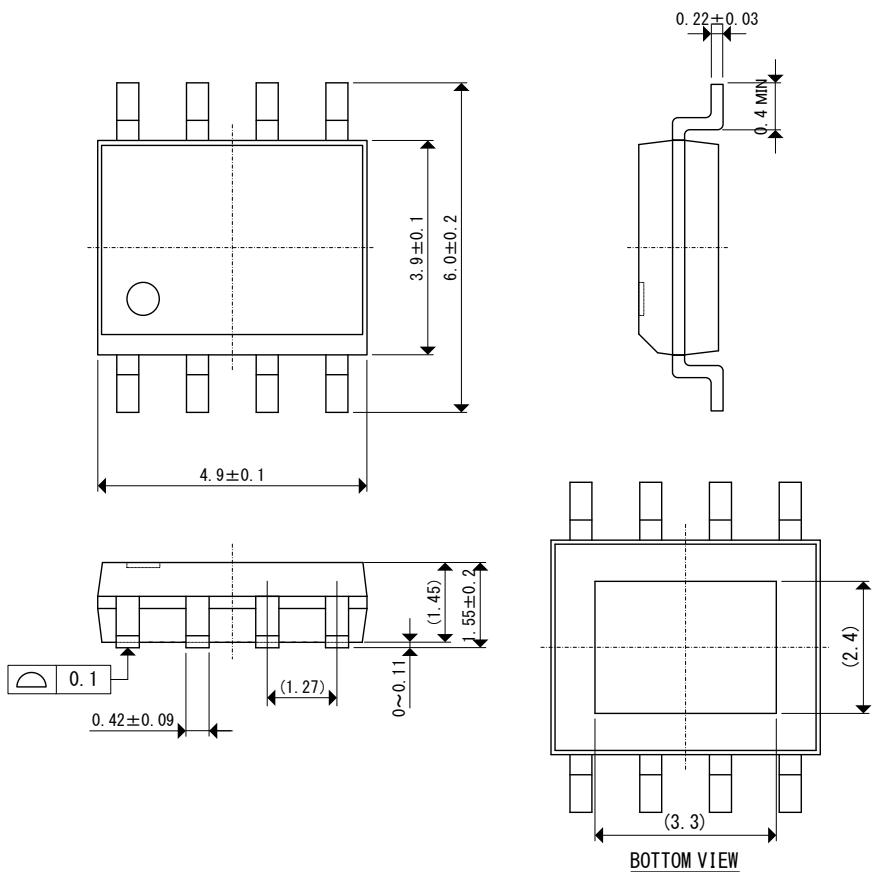


●SOT-89-5 Reference Pattern Layout (unit: mm)

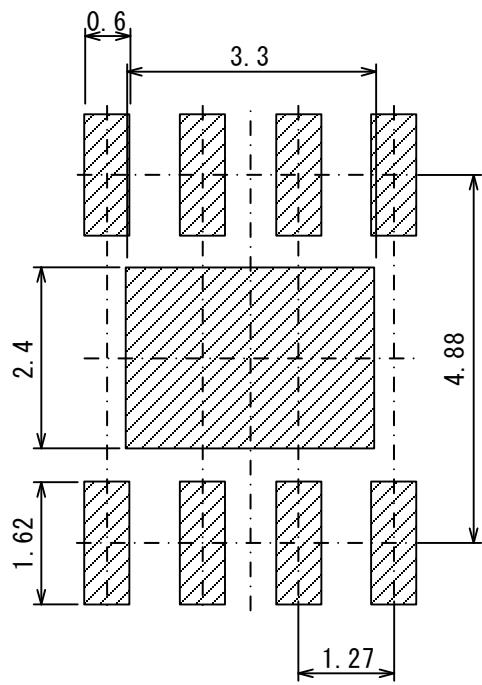


■PACKAGING INFORMATION (Continued)

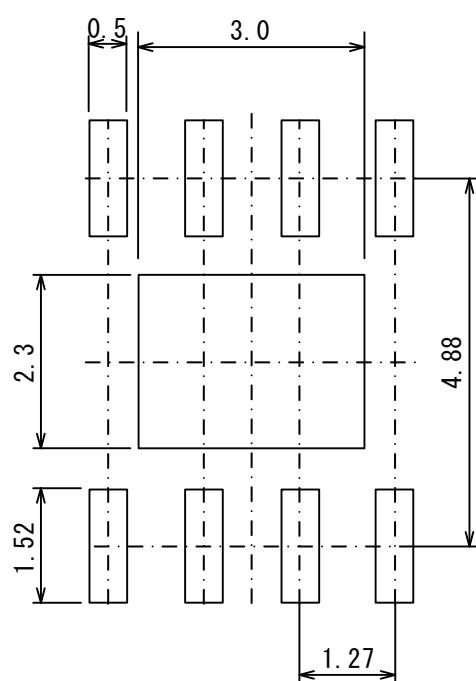
●SOP-8FD (unit: mm)



●SOP-8FD Reference Pattern Layout (unit: mm)



●SOP-8FD Reference Metal Mask (unit: mm)



USP-6C Power Dissipation

Power dissipation data for the USP-6C is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition : Mount on a board

Ambient : Natural convection

Soldering : Lead (Pb) free

Board : Dimensions 40mmx40mm(1600mm² in one side)

Copper (Cu) traces occupy 50% of the board area

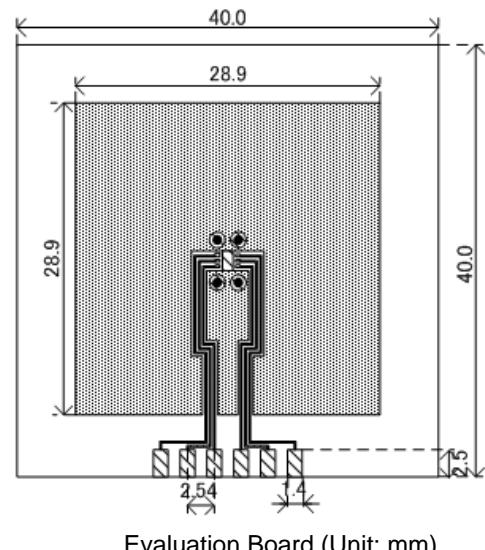
In top and back faces

Package heat - sink is tied to the copper traces

Material : Glass Epoxy (FR-4)

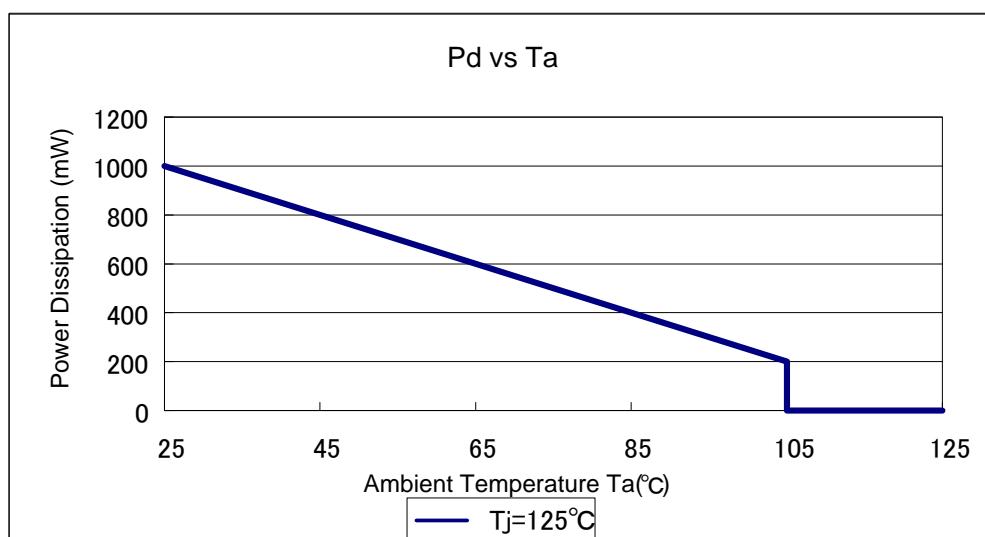
Thickness : 1.6mm

Through - hole : 4 x 0.8 Diameter

**2. Power Dissipation vs. Ambient Temperature**

Board Mount(T_{jmax}=125°C)

Ambient Temperature(°C)	Power Dissipation Pd (mW)	Thermal Resistance(°C/W)
25	1000	100.00
105	200	



■PACKAGING INFORMATION (Continued)

SOT-89-5 Power Dissipation

Power dissipation data for the SOT-89-5 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition : Mount on a board

Ambient : Natural convection

Soldering : Lead (Pb) free

Board : Dimensions 40x 40mm (1600mm² in one side)

Copper (Cu) traces occupy 50% of the board area

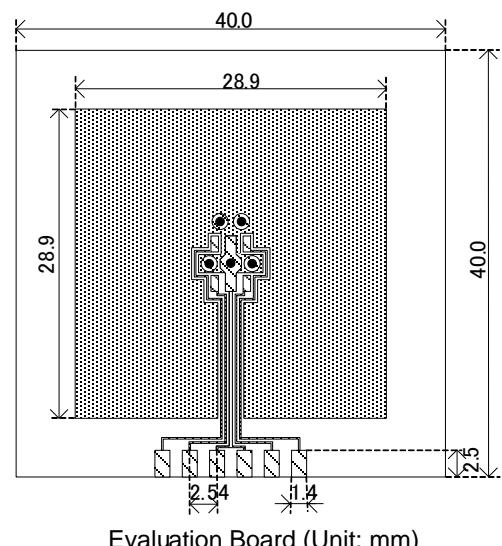
In top and back faces

Package heat- sink is tied to the copper traces

Material : Glass Epoxy (FR-4)

Thickness :1.6mm

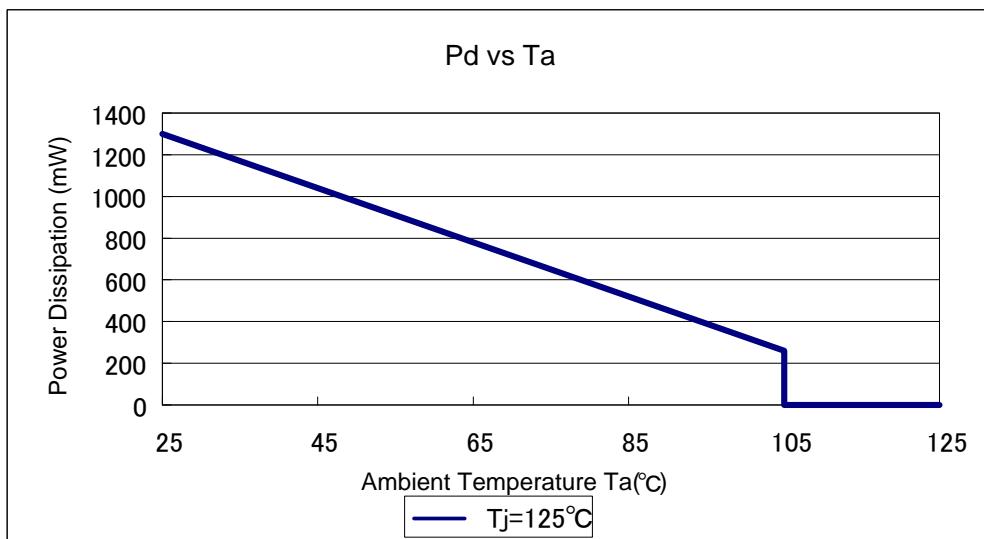
Through -hole :5 x 0.8 Diameter



2. Power Dissipation vs. Ambient Temperature

Board Mount (Tjmax=125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	1300	76.92
105	260	



■PACKAGING INFORMATION (Continued)

SOP - 8FD Power Dissipation(40x40Two Layer)

Power dissipation data for the SOP - 8FD is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition : Mount on a board

Ambient : Natural convection

Soldering : Lead (Pb) free

Board : Dimensions 40x40 mm (1600 mm²in one side)

Copper (Cu) traces occupy 50% of the board area

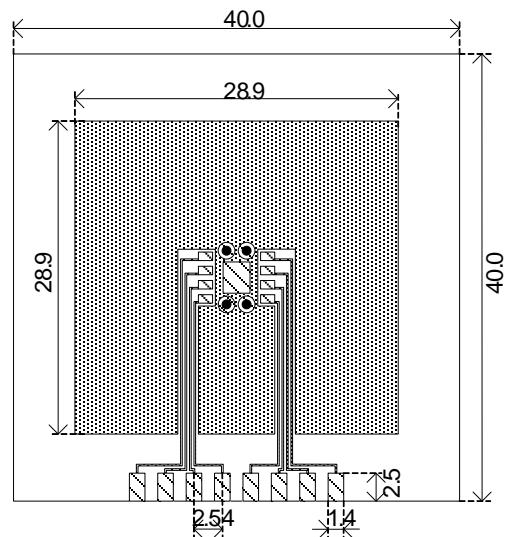
In top and back faces

Package heat-sink is tied to the copper traces

Material : Glass Epoxy (FR-4)

Thickness : 1.6 mm

Through-hole : 4 x 0.8 Diameter

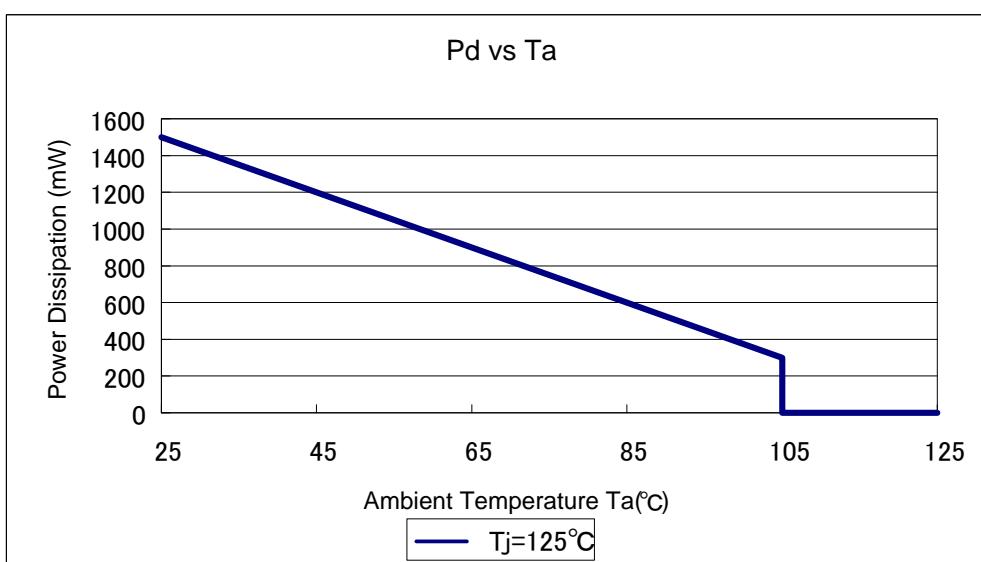


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature

Board Mount (Tjmax=125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	1500	66.67
105	300	



■ MARKING RULE

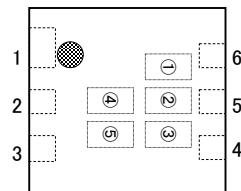
USP-6C

● USP-6C / SOT-89-5 / SOP-8FD

(mark header: ①~③) *mark header does not change with a lot.

① represents product series

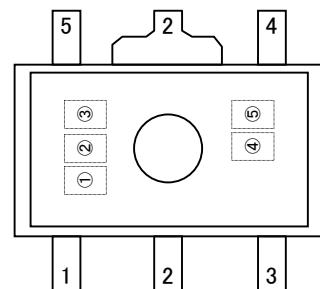
MARK	PRODUCT SERIES
V	XC6702*****



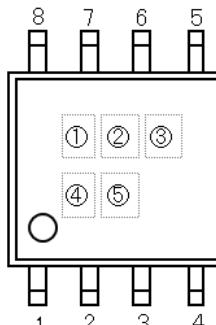
SOT89-5

② represents type of regulators and output voltage

MARK	TYPE	OUTPUT VOLTAGE(V)	PRODUCT SERIES
4	D	1.8~3.0	XC6702D***** -G
5		3.1~6.0	
6		6.1~9.0	
7		9.1~12.0	
C		12.1~15.0	
D		15.1~18.0	



SOP-8FD



③ represents output voltage

MARK	OUTPUT VOLTAGE (V)					MARK	OUTPUT VOLTAGE (V)						
0	-	3.1	6.1	9.1	12.1	15.1	F	-	4.6	7.6	10.6	13.6	16.6
1	-	3.2	6.2	9.2	12.2	15.2	H	-	4.7	7.7	10.7	13.7	16.7
2	-	3.3	6.3	9.3	12.3	15.3	K	1.8	4.8	7.8	10.8	13.8	16.8
3	-	3.4	6.4	9.4	12.4	15.4	L	1.9	4.9	7.9	10.9	13.9	16.9
4	-	3.5	6.5	9.5	12.5	15.5	M	2.0	5.0	8.0	11.0	14.0	17.0
5	-	3.6	6.6	9.6	12.6	15.6	N	2.1	5.1	8.1	11.1	14.1	17.1
6	-	3.7	6.7	9.7	12.7	15.7	P	2.2	5.2	8.2	11.2	14.2	17.2
7	-	3.8	6.8	9.8	12.8	15.8	R	2.3	5.3	8.3	11.3	14.3	17.3
8	-	3.9	6.9	9.9	12.9	15.9	S	2.4	5.4	8.4	11.4	14.4	17.4
9	-	4.0	7.0	10.0	13.0	16.0	T	2.5	5.5	8.5	11.5	14.5	17.5
A	-	4.1	7.1	10.1	13.1	16.1	U	2.6	5.6	8.6	11.6	14.6	17.6
B	-	4.2	7.2	10.2	13.2	16.2	V	2.7	5.7	8.7	11.7	14.7	17.7
C	-	4.3	7.3	10.3	13.3	16.3	X	2.8	5.8	8.8	11.8	14.8	17.8
D	-	4.4	7.4	10.4	13.4	16.4	Y	2.9	5.9	8.9	11.9	14.9	17.9
E	-	4.5	7.5	10.5	13.5	16.5	Z	3.0	6.0	9.0	12.0	15.0	18.0

④,⑤ represents production lot number

01~09, 0A~0Z, 11~9Z, A1~A9, AA~AZ, B1~ZZ in order.

(G, I, J, O, Q, W excluded)

* No character inversion used.

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